

# HITACHI

**SM0065****42PMA225EZ**

SERVICE MANUAL  
MANUEL D'ENTRETIEN  
WARTUNGSHANDBUCH

**CAUTION:**

Before servicing this chassis, it is important that the service technician read the "Safety Precautions" and "Product Safety Notices" in this service manual.

**ATTENTION:**

Avant d'effectuer l'entretien du châassis, le technicien doit lire les «Précautions de sécurité» et les «Notices de sécurité du produit» présentés dans le présent manuel.

**VORSICHT:**

Vor Öffnen des Gehäuses hat der Service-Ingenieur die „Sicherheitshinweise“ und „Hinweise zur Produktsicherheit“ in diesem Wartungshandbuch zu lesen.

Data contained within this Service manual is subject to alteration for improvement.

Les données fournies dans le présent manuel d'entretien peuvent faire l'objet de modifications en vue de perfectionner le produit.

Die in diesem Wartungshandbuch enthaltenen Spezifikationen können sich zwecks Verbesserungen ändern.

SPECIFICATIONS AND PARTS ARE SUBJECT TO CHANGE FOR IMPROVEMENT

**Colour Television**  
**September 2004**

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## 1. INTRODUCTION

42" Plasma TV is a progressive TV control system with built-in **de-interlacer** and **scaler**. It uses a 852\*480 panel with 16:9 aspect ratio. The TV is capable of operation in PAL, SECAM, NTSC (playback) colour standards and multiple transmission standards as B/G, D/K, I/I', and L/L' including German and NICAM stereo. Sound system output is supplying 2x10W (10%THD) for stereo 8Ω speakers. The chassis is equipped with many inputs and outputs allowing it to be used as a center of a media system.

It supports following peripherals:

2 SCART's with all of them supporting full SCART features including RGB input

1 AV inputs. (CVBS+ Stereo Audio)

1 SVHS input

1 Stereo Headphone output

1 D-Sub 15 PC input

1 DVI input

1 Stereo audio input for PC/DVI

Other features include, Picture-In-Picture (PIP) , Picture-And-Picture (PAP) .

## 2. MULTI STANDARD SOUND PROCESSOR

The MSP34x1G family of single-chip Multistandard Sound Processors covers the sound processing of all analog TV-Standards worldwide, as well as the NICAM digital sound standards. The full TV sound processing, starting with analog sound IF signal-in, down to processed analog AF-out, is performed on a single chip.

These TV sound processing ICs include versions for processing the multichannel television sound (MTS) signal conforming to the standard recommended by the Broadcast Television Systems Committee (BTSC). The DBX noise reduction, or alternatively, Micronas Noise Reduction (MNR) is performed alignment free. Other processed standards are the Japanese FM-FM multiplex standard (EIA-J) and the FM Stereo Radio standard.

Current ICs have to perform adjustment procedures in order to achieve good stereo separation for BTSC and EIA-J. The MSP34x1G has optimum stereo performance without any adjustments.

## 3. VIDEO SWITCH TEA6415

In case of three or more external sources are used, the video switch IC TEA6415 is used. The main function of this device is to switch 8 video-input sources on the 6 outputs.

Each output can be switched on only one of each input. On each input an alignment of the lowest level of the signal is made (bottom of sync. top for CVBS or black level for RGB signals).

Each nominal gain between any input and output is 6.5dB. For D2MAC or Chroma signal the alignment is switched off by forcing, with an external resistor bridge, 5VDC on the input. Each input can be used as a normal input or as a MAC or Chroma input (with external Resistor Bridge). All the switching possibilities are changed through the BUS. Driving 75ohm load needs an external resistor. It is possible to have the same input connected to several outputs.

## 4. AUDIO AMPLIFIER STAGE WITH TDA8928ST

The TDA8928ST is a switching power stage for high efficiency class-D audio power amplifier system. With this power stage a compact 2x10 W Self Oscillating Digital Amplifier System (SODA) can be built, operating with high efficiency and very low dissipation. No heat sink is required. The system operates over a wide supply voltage range from ±7.5 V to ±30 V and consumes a very low quiescent current.

## 5. POWER SUPPLY (SMPS)

The DC voltages required at various parts of the chassis are provided by an SMPS transformer controlled by the IC MC44608, which is designed for driving, controlling and protecting switching transistor of SMPS. The transformer generates 145V for FBT input, +/-14V for audio amplifier, 5V and 3.3V stand by voltage and 33V, 12V and 5V supplies for other different parts of the chassis.

An optocoupler is used to control the regulation of line voltage and stand-by power consumption. There is a regulation circuit in secondary side. This circuit produces a control voltage according to the changes in 145V DC voltage, via an optocoupler (TCET1102G) to pin3 of the IC.

During the switch on period of the transistor, energy is stored in the transformer. During the switch off period energy is fed to the load via secondary winding. By varying switch-on time of the power

transistor, it controls each portion of energy transferred to the second side such that the output voltage remains nearly independent of load variations.

## **6. MICROCONTROLLER**

The microprocessor is embedded inside PW181 chip which also handles scaling, frame rate conversion and OSD generation. The on-chip 16-bit microprocessor is a Turbo x86-compatible processor core with on-chip peripherals (timers, interrupt controller, 2-wire serial master/slave interface, UART, I/O ports, and more). Special peripherals such as Infrared (IR) pulse decoders and a digital pulse width modulator (PWM) are also included. There are two independent 2-wire serial master/slave interface modules that can be multiplexed to control up to five 2-wire serial ports. The slave 2-wire interface is designed for HDCP use only (and requires the use of HDCP Image Processors). On-chip RAM of up to 64 Kbytes is available. A complete microprocessor system can be implemented simply by adding external ROM. The on-chip processor can be disabled to allow external processor control of all internal functions.

## **7. SERIAL ACCESS CMOS 4K x 8 (32K bit) EEPROM 24C32A**

The Microchip Technology Inc. 24C32A is a 4K x 8 (32K bit) Serial Electrically Erasable PROM. It has been developed for advanced, low power applications such as personal communications or data acquisition. The 24C32A also has a page-write capability of up to 32 bytes of data. The 24C32A is capable of both random and sequential reads up to the 32K boundary. Functional address lines allow up to eight 24C32A devices on the same bus, for up to 256K bits address space. Advanced CMOS technology and broad voltage range make this device ideal for low-power/low-voltage, non-volatile code and data applications.

## **8. CLASS AB STEREO HEADPHONE DRIVER TDA1308**

The TDA1308 is an integrated class AB stereo headphone driver contained in a DIP8 plastic package. The device is fabricated in a 1 mm CMOS process and has been primarily developed for portable digital audio applications.

## **9. IC DESCRIPTIONS AND INTERNAL BLOCK DIAGRAM**

TEA6415C  
24C32  
LM317T  
ST24LC21  
TLC7733  
74LVC257A  
74LVC14A  
TEA6420D  
LM1086  
LM1117  
DS90C385  
TL431  
MSP3411G  
TDA7265  
TDA1308  
PI5V330  
AD9883A  
SAA7118E  
TPS72501  
TSOP1836  
PCF8591  
PW1231  
PW181  
SIL151B  
SDRAM 4M x 16 (MT48LC4M16A2TG-75)  
FLASH

## 9.1. TEA6415C

### 9.1.1. General Description

The main function of the IC is to switch 8 video input sources on 6 outputs. Each output can be switched on only one of each input. On each input an alignment of the lowest level of the signal is made (bottom of synch. top for CVBS or black level for RGB signals). Each nominal gain between any input and output is 6.5dB. For D2MAC or Chroma signal the alignment is switched off by forcing, with an external resistor bridge, 5 V<sub>DC</sub> on the input. Each input can be used as a normal input or as a MAC or Chroma input (with external resistor bridge). All the switching possibilities are changed through the BUS. Driving 75Ω load needs an external transistor. It is possible to have the same input connected to several outputs. The starting configuration upon power on (power supply: 0 to 10V) is undetermined. In this case, 6 words of 16 bits are necessary to determine one configuration. In other case, 1 word of 16 bits is necessary to determine one configuration.

### 9.1.2. Features

- 20MHz Bandwidth
- Cascadable with another TEA6415C (Internal address can be changed by pin 7 voltage)
- 8 Inputs (CVBS, RGB, MAC, CHROMA,)
- 6 Outputs
- Possibility of MAC or chroma signal for each input by switching-off the clamp with an external resistor bridge
- Bus controlled
- 6.5dB gain between any input and output
- 55dB crosstalk at 5 MHz
- Fully ESD protected

### 9.1.3. Pinning

1.	Input	:	Max	: 2Vpp, Input Current: 1mA, Max: 3mA
2.	Data	:	Low level	: -0.3V Max: 1.5V,
			High level	: 3.0V Max : Vcc+0.5V
3.	Input	:	Max	: 2Vpp, Input Current: 1mA, Max : 3mA
4.	Clock	:	Low level	: -0.3V Max: 1.5V,
			High level	: 3.0V Max : Vcc+0.5V
5.	Input	:	Max	: 2Vpp, Input Current: 1mA, Max: 3mA
6.	Input	:	Max	: 2Vpp, Input Current: 1mA, Max: 3mA
7.	Prog			
8.	Input	:	Max	: 2Vpp, Input Current: 1mA, Max: 3mA
9.	Vcc	:	12V	
10.	Input	:	Max	: 2Vpp, Input Current: 1mA, Max: 3mA
11.	Input	:	Max	: 2Vpp, Input Current: 1mA, Max: 3mA
12.	Ground			
13.	Output	:	5.5Vpp,	Min: 4.5Vpp
14.	Output	:	5.5Vpp,	Min: 4.5Vpp
15.	Output	:	5.5Vpp,	Min: 4.5Vpp
16.	Output	:	5.5Vpp,	Min: 4.5Vpp
17.	Output	:	5.5Vpp,	Min: 4.5Vpp
18.	Output	:	5.5Vpp,	Min: 4.5Vpp
19.	Ground			
20.	Input	:	Max: 2Vpp, Input Current	: 1mA, Max : 3mA

## 9.2. 24C32A

### 9.2.1. Features

- Voltage operating range: 4.5V to 5.5V
- Maximum write current 3 mA at 5.5V

- Standby current 1 mA typical at 5.0V
- 2-wire serial interface bus, I<sup>2</sup>C™ compatible
- 100 kHz and 400 kHz compatibility
- Self-timed ERASE and WRITE cycles
- Power on/off data protection circuitry
- Hardware write protect
- 1,000,000 Erase/Write cycles guaranteed
- 32-byte page or byte write modes available
- Schmitt trigger filtered inputs for noise suppression
- Output slope control to eliminate ground bounce
- 2 ms typical write cycle time, byte or page
- Up to eight devices may be connected to the same bus for up to 256K bits total memory
- Electrostatic discharge protection > 4000V
- Data retention > 200 years
- 8-pin PDIP and SOIC packages
- Temperature ranges
  - Commercial (C): 0°C to 70°C
  - Industrial (I): -40°C to +85°C
  - Automotive (E): -40°C to +125°C

### 9.2.2. Description

The Microchip Technology Inc. 24C32A is a 4K x 8 (32K bit) Serial Electrically Erasable PROM. It has been developed for advanced, low power applications such as personal communications or data acquisition. The 24C32A also has a page-write capability of up to 32 bytes of data. The 24C32A is capable of both random and sequential reads up to the 32K boundary. Functional address lines allow up to eight 24C32A devices on the same bus, for up to 256K bits address space. Advanced CMOS technology and broad voltage range make this device ideal for low-power/low-voltage, non-volatile code and data applications. The 24C32A is available in the standard 8-pin plastic DIP and both 150 mil and 200 mil SOIC packaging.

### 9.2.3. Pin Function table

Name	Function
A0, A1, A2	User Configurable Chip Selects
V <sub>ss</sub>	Ground
SDA	Serial Address/Data I/O
SCL	Serial Clock
WP	Write Protect Input
V <sub>cc</sub>	+4.5V to 5.5V Power Supply

#### **9.2.4. Functional Descriptions**

The 24C32A supports a Bi-directional 2-wire bus and data transmission protocol. A device that sends data onto the bus is defined as transmitter, and a device receiving data as receiver. The bus must be controlled by a master device which generates the Serial Clock (SCL), controls the bus access, and generates the START and STOP conditions, while the 24C32A works as slave. Both master and slave can operate as transmitter or receiver but the master device determines which mode is activated.

### **9.3. LM317**

#### **9.3.1. General Description**

The LM117/LM217/LM317 are monolithic integrated circuit in TO-220, ISOWATT220, TO-3 and D 2 PAK packages intended for use as positive adjustable voltage regulators.

They are designed to supply more than 1.5A of load current with an output voltage adjustable over a 1.2 to 37V range.

The nominal output voltage is selected by means of only a resistive divider, making the device exceptionally easy to use and eliminating the stocking of many fixed regulators.

#### **9.3.2. Features**

- Output voltage range: 1.2 to 37V
- Output current in excess of 1.5A
- 0.1% Line and Load Regulation
- Floating Operation for High Voltages
- Complete Series of Protections: Current Limiting, Thermal Shutdown And Soa Control

### **9.4. ST24LC21**

#### **9.4.1. Description**

The ST24LC21 is a 1K bit electrically erasable programmable memory (EEPROM), organized by 8 bits. This device can operate in two modes: Transmit Only mode and I<sup>2</sup>C bidirectional mode. When powered, the device is in Transmit Only mode with EEPROM data clocked out from the rising edge of the signal applied on VCLK. The device will switch to the I<sup>2</sup>C bidirectional mode upon the falling edge of the signal applied on SCL pin. The ST24LC21 can not switch from the I<sup>2</sup>C bidirectional mode to the Transmit Only mode (except when the power supply is removed). The device operates with a power supply value as low as 2.5V. Both Plastic Dual-in-Line and Plastic Small Outline packages are available.

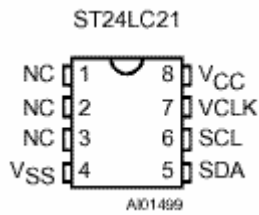
#### **9.4.2. Features**

- 1 million Erase/Write cycles
- 40 years data retention
- 2.5V To 5.5V single supply voltage
- 400k Hz compatibility over the full range of supply voltage
- Two wire serial interface I<sup>2</sup>C bus compatible
- Page Write (Up To 8 Bytes)
- Byte, random and sequential read modes
- Self timed programming cycle
- Automatic address incrementing
- Enhanced ESD/Latch up
- Performances

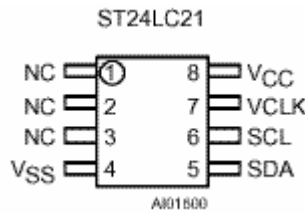


### 9.4.3. Pin connections

DIP Pin connections



CO Pin connections



NC: Not connected

### Signal names

SDA	Serial data Address Input/Output
SCL	Serial Clock (I <sup>2</sup> C mode)
V <sub>cc</sub>	Supply voltage
V <sub>ss</sub>	Ground
VCLK	Clock transmit only mode

## 9.5. TLC7733

### 9.5.1. Description

The TLC77xx family of micro power supply voltage supervisors is designed for reset control, primarily in microcomputer and microprocessor systems.

During power-on, RESET is asserted when V<sub>DD</sub> reaches 1 V. After minimum V<sub>DD</sub> (. 2 V) is established, the circuit monitors SENSE voltage and keeps the reset outputs active as long as SENSE voltage (V<sub>I(SENSE)</sub>)

remains below the threshold voltage. An internal timer delays return of the output to the inactive state to ensure proper system reset. The delay time, t<sub>d</sub>, is determined by an external capacitor:

$$t_d = 2.1 \times 10^4 \times C_T$$

Where

C<sub>T</sub> is in farads

t<sub>d</sub> is in seconds

The TLC77xx has a fixed SENSE threshold voltage set by an internal voltage divider. When SENSE voltage drops below the threshold voltage, the outputs become active and stay in that state until SENSE voltage returns above threshold voltage and the delay time, t<sub>d</sub>, has expired.

In addition to the power-on-reset and under voltage-supervisor function, the TLC77xx adds power-down control support for static RAM. When CONTROL is tied to GND, RESET will act as active high. The voltage monitor contains additional logic intended for control of static memories with battery backup during power failure. By driving the chip select (CS) of the memory circuit with the RESET output of the TLC77xx and with the CONTROL driven by the memory bank select signal (CSH1) of the microprocessor (see Figure 10), the memory circuit is automatically disabled during a power loss. (In this application the TLC77xx power has to be supplied by the battery.)

The TLC77xxQ is characterized for operation over a temperature range of -40°C to 125°C, and the TLC77xxL is characterized for operation over a temperature range of -40°C to 85°C.

## 9.6. 74LVC257A

### 9.6.1. Features

Wide supply voltage range of 1.2 to 3.6 V  
In accordance with JEDEC standard no. 8-1A  
CMOS lower power consumption  
Direct interface with TTL levels  
Output drive capability 50 \_ transmission lines at 85°C  
5 Volt tolerant inputs/outputs, for interfacing with 5 Volt logic

### 9.6.2. Description

The 74LVC257A is a high-performance, low-power, low-voltage, Si-gate CMOS device and superior to most advanced CMOS compatible TTL families.

Inputs can be driven from either 3.3V or 5.0V devices. In 3-State operation, outputs can handle 5V. This feature allows the use of these devices as translators in a mixed 3.3V/5V environment.

The 74LVC257A is a quad 2-input multiplexer with 3-state outputs, which select 4 bits of data from two sources and are controlled by a common data select input (S). The data inputs from source 0 (1I 0 to 4I 0 ) are selected when input S is LOW and the data inputs from source 1 (1I 1 to 4I 1 ) are selected when S is HIGH. Data appears at the outputs (1Y to 4Y) in true (non-inverting) form from the selected inputs. The 74LVC257A is the logic implementation of a 4-pole, 2-position switch, where the position of the switch is determined by the logic levels applied to S. The outputs are forced to a high impedance OFF-state when OE is HIGH.

### 9.6.3. Pin Description

PIN NUMBER	SYMBOL	DESCRIPTION
1	S	Common data select input
2, 5, 11, 14	1  <sub>0</sub> to 4  <sub>0</sub>	Data inputs from source 0
3, 6, 10, 13	1  <sub>1</sub> to 4  <sub>1</sub>	Data outputs from source 1
4,7,9,12	1Y to 4Y	3-State multiplexer outputs
8	GND	Ground (0V)
15	OE	3-State output enable input (active LOW)
16	V <sub>cc</sub>	Positive supply voltage

## 9.7. 74LVC14A

### 9.7.1. Features

- Wide supply voltage range of 1.2 to 3.6 V
- In accordance with JEDEC standard no. 8-1A
- Inputs accept voltages up to 5.5 V
- CMOS low power consumption
- Direct interface with TTL levels

### 9.7.2. Applications

- Wave and pulse shapers for highly noisy environments
- Astable multivibrators
- Monostable multivibrators

### 9.7.3. Description

The 74LVC14A is a high-performance, low power, low-voltage Si-gate CMOS device and superior to most advanced CMOS compatible TTL families.

Inputs can be driven from either 3.3 V or 5 V devices. This feature allows the use of these devices as translators in a mixed 3.3 V/5 V environment.

The 74LVC14A provides six inverting buffers with Schmitt-trigger action. It is capable of transforming slowly changing input signals into sharply defined, jitter-free output signals.

#### 9.7.4. Pin Description

PIN NUMBER	SYMBOL	DESCRIPTION
1, 3, 5, 9, 11, 13	1A – 6A	Data inputs
2, 4, 6, 8, 10, 12	1Y – 6Y	Data outputs
7	GND	Ground (0V)
14	V <sub>CC</sub>	Positive supply voltage

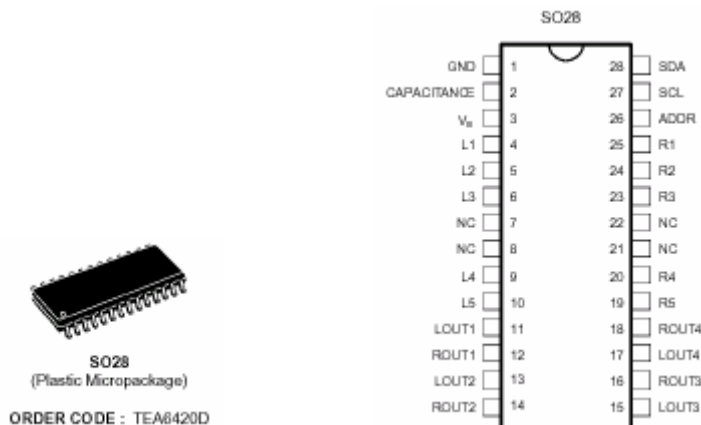
### 9.8. TEA6420

#### 9.8.1. Features

- 5 Stereo Inputs
- 4 Stereo Outputs
- Gain Control 0/2/4/6db/Mute for Each Output
- Cascadable (2 Different Addresses)
- Serial Bus Controlled
- Very Low noise
- Very Low distortion

#### 9.8.2. Description

The TEA6420 switches 5 stereo audio inputs on 4 stereo outputs. All the switching possibilities are changed through the I<sup>2</sup>C bus.



### 9.9. LM1086

#### 9.9.1. Description

The LM1086 is a series of low dropout positive voltage regulators with a maximum dropout of 1.5V at 1.5A of load current. It has the same pin-out as National Semiconductor's industry standard LM317. The LM1086 is available in an adjustable version, which can set the output voltage with only two external resistors. It is also available in five fixed voltages: 2.5V, 2.85V, 3.3V, 3.45V and 5.0V. The fixed versions integrate the adjust resistors. The LM1086 circuit includes a zener trimmed band-gap reference, current limiting and thermal shutdown.

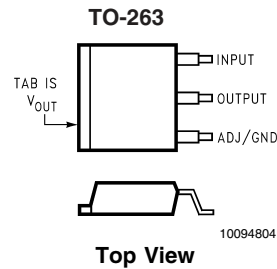
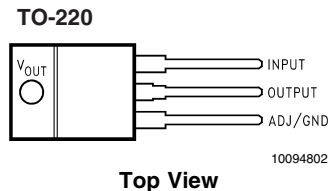
#### 9.9.2. Features

- Available in 2.5V, 2.85V, 3.3V, 3.45V, 5V and Adjustable Versions
- Current Limiting and Thermal Protection
- Output Current 1.5A
- Line Regulation 0.015% (typical)
- Load Regulation 0.1% (typical)

### 9.9.3. Applications

- SCSI-2 Active Terminator
- High Efficiency Linear Regulators
- Battery Charger
- Post Regulation for Switching Supplies
- Constant Current Regulator
- Microprocessor Supply

### 9.9.4. Connection Diagrams



## 9.10. LM1117

### 9.10.1. General Description

The LM1117 is a series of low dropout voltage regulators with a dropout of 1.2V at 800mA of load current. It has the same pin-out as National Semiconductor's industry standard LM317. The LM1117 is available in an adjustable version, which can set the output voltage from 1.25V to 13.8V with only two external resistors. In addition, it is also available in five fixed voltages, 1.8V, 2.5V, 2.85V, 3.3V, and 5V. The LM1117 offers current limiting and thermal shutdown. Its circuit includes a zener trimmed bandgap reference to assure output voltage accuracy to within  $\pm 1\%$ . The LM1117 series is available in SOT-223, TO-220, and TO-252 D-PAK packages. A minimum of 10 $\mu$ F tantalum capacitor is required at the output to improve the transient response and stability.

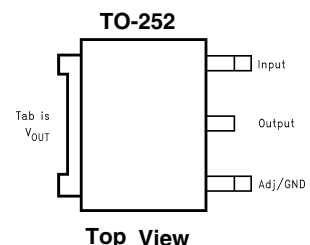
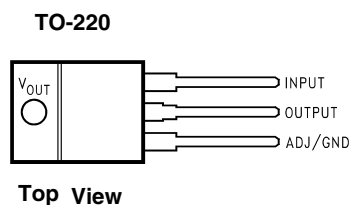
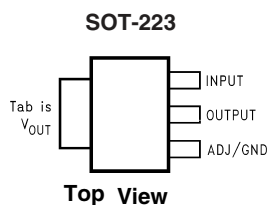
### 9.10.2. Features

- Available in 1.8V, 2.5V, 2.85V, 3.3V, 5V, and Adjustable Versions
- Space Saving SOT-223 Package
- Current Limiting and Thermal Protection
- Output Current 800mA
- Line Regulation 0.2% (Max)
- Load Regulation 0.4% (Max)
- Temperature Range
  - LM1117 0°C to 125°C
  - LM1117I -40°C to 125°C

### 9.10.3. Applications

- 2.85V Model for SCSI-2 Active Termination
- Post Regulator for Switching DC/DC Converter
- High Efficiency Linear Regulators
- Battery Charger
- Battery Powered Instrumentation

### 9.10.4. Connection Diagrams



## 9.11. DS90C385

### 9.11.1. General Description

The DS90C385 transmitter converts 28 bits of LVCMOS/LVTTL data into four LVDS (Low Voltage Differential Signalling) data streams. A phase-locked transmit clock is transmitted in parallel with the data streams over a fifth LVDS link.

Every cycle of the transmit clock 28 bits of input data are sampled and transmitted. At a transmit clock frequency of 85 MHz, 24 bits of RGB data and 3 bits of LCD timing and control data (FPLINE, FPFRAFRAME, DRDY) are transmitted at a rate of 595 Mbps per LVDS data channel. Using an 85 MHz clock, the data throughput is 297.5 Mbytes/sec. Also available is the DS90C365 that converts 21 bits of LVCMOS/LVTTL data into three LVDS (Low Voltage Differential Signalling) data streams. Both transmitters can be programmed for Rising edge strobe or falling edge strobe through a dedicated pin. A Rising edge or Falling edge strobe transmitter will interoperate with a Falling edge strobe Receiver (DS90CF386/DS90CF366) without any translation logic.

The DS90C385 is also offered in a 64 ball, 0.8mm fine pitch ball grid array (FBGA) package which provides a 44 % reduction in PCB footprint compared to the TSSOP package. This chipset is an ideal means to solve EMI and cable size problems associated with wide, high-speed TTL interfaces.

### 9.11.2. Features

- 20 to 85 MHz shift clock support
- Best-in-Class Set & Hold Times on TxINPUTs
- Tx power consumption <130 mW (typ) @85MHz Grayscale
- Tx Power-down mode <200µW (max)
- Supports VGA, SVGA, XGA and Dual Pixel SXGA.
- Narrow bus reduces cable size and cost
- Up to 2.38 Gbps throughput
- Up to 297.5 Megabytes/sec bandwidth
- 345 mV (typ) swing LVDS devices for low EMI
- PLL requires no external components
- Compatible with TIA/EIA-644 LVDS standard
- Low profile 56-lead or 48-lead TSSOP package
- DS90C385 also available in a 64 ball, 0.8mm fine pitch ball grid array (FBGA) package

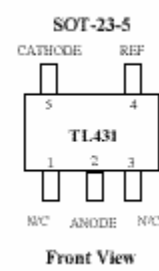
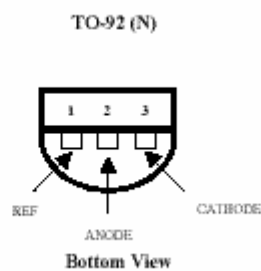
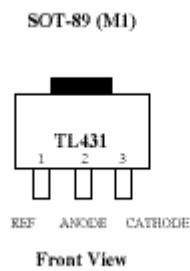
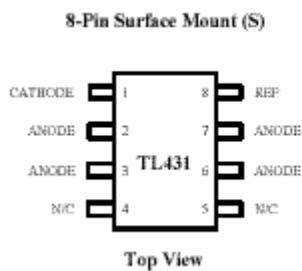
### 9.11.3. Pin Description

#### DS90C385 MTD56 (TSSOP) Package Pin Description-FPD Link Transmitter

Pin Name	I/O	No.	Description
TxIN	I	28	TTL level input. This includes: 8 Red, 8 Green, 8 Blue, and 4 control lines —FPLINE, FPFRAFRAME and DRDY (also referred to as HSYNC, VSYNC, Data Enable).
TxOUT+	O	4	Positive LVDS differential data output.
TxOUT-	O	4	Negative LVDS differential data output.
TxCLKIN	I	1	TTL level clock input. Pin name TxCLK IN.
R_FB	I	1	Programmable strobe select
TxCLK OUT+	O	1	Positive LVDS differential clock output.
TxCLK OUT-	O	1	Negative LVDS differential clock output.
PWR DOWN	I	1	TTL level input. Assertion (low input) TRI-STATES the outputs, ensuring low current at power down.
Vcc	I	3	Power supply pins for TTL inputs.
GND	I	4	Ground pins for TTL inputs.
PLL Vcc	I	1	Power supply pin for PLL.
PLL GND	I	2	Ground pins for PLL.
LVDS Vcc	I	1	Power supply pin for LVDS outputs.
LVDS GND	I	3	Ground pins for LVDS outputs.

## DS90C385SLC SLC64A Package Pin Description-FPD Link Transmitter

Pin Name	I/O	No.	Description
TxIN	I	28	TTL level input.
TxOUT+	O	4	Positive LVDS differential data output.
TxOUT-	O	4	Negative LVDS differential data output.
TxCLKIN	I	1	TTL level clock input. The rising edge acts as data strobe. Pin name TxCLK IN.
R_FB	I	1	Programmable strobe select. HIGH = rising edge, LOW = falling edge.
TxCLK OUT+	O	1	Positive LVDS differential clock output.
TxCLK OUT-	O	1	Negative LVDS differential clock output.
PWR DOWN	I	1	TTL level input. Assertion (low input) TRI-STATES the outputs, ensuring low current at power down.
Vcc	I	3	Power supply pins for TTL inputs.
GND	I	5	Ground pins for TTL inputs.
PLL Vcc	I	1	Power supply pin for PLL.
PLL GND	I	2	Ground pins for PLL.
LVDS Vcc	I	2	Power supply pin for LVDS outputs.
LVDS GND	I	4	Ground pins for LVDS outputs.
NC		6	Pins not connected.



## 9.12. MSP34X1G

MSP3411G

### Multistandard Sound Processor Family

#### 9.12.1. Introduction

The MSP 34x1G family of single-chip Multistandard Sound Processors covers the sound processing of all analog TV-Standards worldwide, as well as the NICAM digital sound standards. The full TV sound processing, starting with analog sound IF signal-in, down to processed analog AF-out, is performed on a single chip. Figure shows a simplified functional block diagram of the MSP 34x1G.

The MSP 34x1G has all functions of the MSP 34x0G with the addition of a virtual surround sound feature.

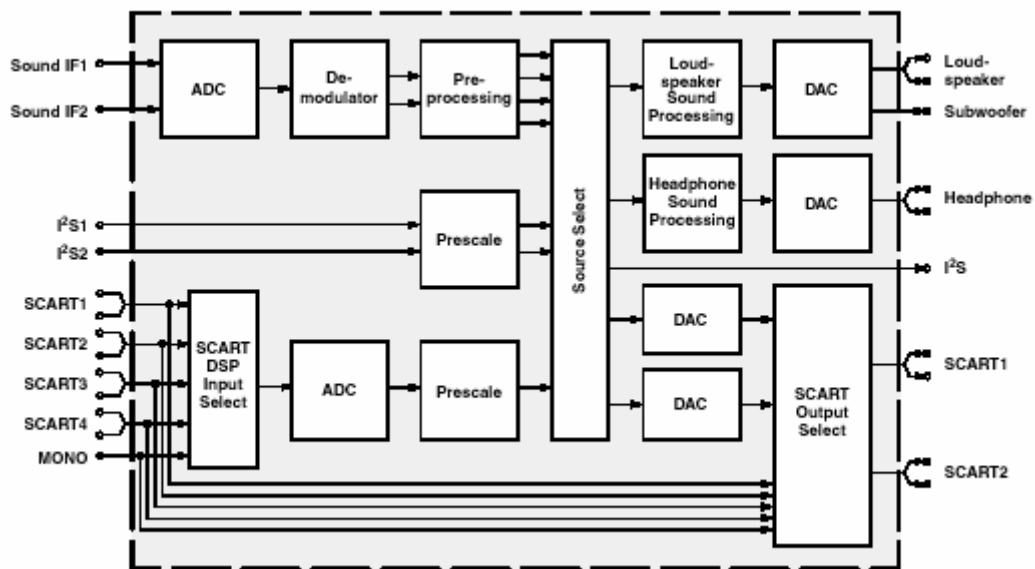
Surround sound can be reproduced to a certain extent with two loudspeakers. The MSP 34x1G includes the Micronas virtualizer algorithm "3D-PANORAMA" which has been approved by the Dolby 1) Laboratories for with the "Virtual Dolby Surround" technology. In addition, the MSP 34x1G includes the "PAN-ORAMA" algorithm.

These TV sound processing ICs include versions for processing the multichannel television sound (MTS) signal conforming to the standard recommended by the Broadcast Television Systems Committee (BTSC). The DBX noise reduction, or alternatively, Micronas Noise Reduction (MNR) is performed alignment free.

Other processed standards are the Japanese FM-FM multiplex standard (EIA-J) and the FM Stereo Radio standard.

Current ICs have to perform adjustment procedures in order to achieve good stereo separation for BTSC and EIA-J. The MSP 34x1G has optimum stereo performance without any adjustments.

The MSP 34x1G has built-in automatic functions: The IC is able to detect the actual sound standard automatically (Automatic Standard Detection). Furthermore, pilot levels and identification signals can be evaluated internally with subsequent switching between mono/stereo/bilingual; no I<sup>2</sup>C interaction is necessary (Automatic Sound Selection).



#### Source Select

I<sup>2</sup>S bus interface consists of five pins:

1. I<sup>2</sup>S\_DA\_IN1, I<sup>2</sup>S\_DA\_IN2: For input, four channels (two channels per line, 2\*16 bits) per sampling cycle (32 kHz) are transmitted.
2. I<sup>2</sup>S\_DA\_OUT: For output, two channels (2\*16 bits) per sampling cycle (32 kHz) are transmitted.
3. I<sup>2</sup>S\_CL: Gives the timing for the transmission of I<sup>2</sup>S serial data (1.024 MHz).
4. I<sup>2</sup>S\_WS: The I<sup>2</sup>S\_WS word strobe line defines the left and right sample.

### 9.12.2. Features

- 3D-PANORAMA virtualizer (approved by Dolby Laboratories) with noise generator
- PANORAMA virtualizer algorithm
- Standard Selection with single I<sup>2</sup>C transmission
- Automatic Sound Selection (mono/stereo/bilingual),
- Automatic Carrier Mute function
- Interrupt output programmable (indicating status change)
- Loudspeaker / Headphone channel with volume, balance, bass, treble, loudness
- AVC: Automatic Volume Correction
- Subwoofer output with programmable low-pass and complementary high-pass filter
- 5-band graphic equalizer for loudspeaker channel
- Spatial effect for loudspeaker channel, processing of all deemphasis filtering
- Two selectable sound IF (SIF) inputs
- Four Stereo SCART (line) inputs, one Mono input; two Stereo SCART outputs
- Complete SCART in/out switching matrix
- Two I<sup>2</sup>S inputs; one I<sup>2</sup>S output
- Automatic Standard Detection of terrestrial TV standards
- Demodulation of the BTSC multiplex signal and the SAP channel
- Alignment free digital DBX noise reduction
- BTSC stereo separation (MSP 3441G also EIA-J) significantly better than specification
- SAP and stereo detection for BTSC system
- Demodulation of the FM-Radio multiplex signal

### 9.12.3. Pin connections

NC = not connected; leave vacant

LV = if not used, leave vacant

OBL = obligatory; connect as described in circuit diagram

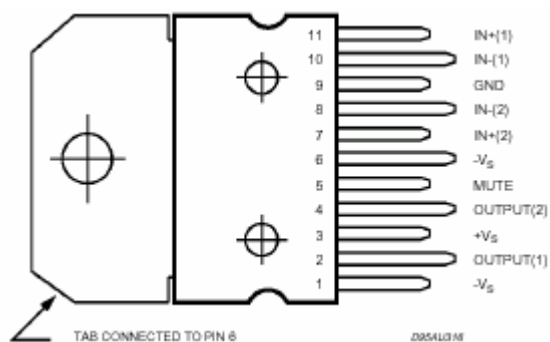
DVSS: if not used, connect to DVSS

AHVSS: connect to AHVSS

Pin No.					Pin Name	Type	Connection (if not used)	Short Description
PLCC 68-pin	PSDIP 64-pin	PSDIP 52-pin	PQFP 80-pin	PLQFP 64-pin				
1	16	14	9	8	ADR_WS	OUT	LV	ADR word strobe
2	-	-	-	-	NC		LV	Not connected
3	15	13	8	7	ADR_DA	OUT	LV	ADR Data Output
4	14	12	7	6	I2S_DA_IN1	IN	LV	I <sup>2</sup> S1 data input
5	13	11	6	5	I2S_DA_OUT	OUT	LV	I <sup>2</sup> S data output
6	12	10	5	4	I2S_WS	IN/OUT	LV	I <sup>2</sup> S word strobe
7	11	9	4	3	I2S_CL	IN/OUT	LV	I <sup>2</sup> S clock
8	10	8	3	2	I2C_DA	IN/OUT	OBL	I <sup>2</sup> C data
9	9	7	2	1	I2C_CL	IN/OUT	OBL	I <sup>2</sup> C clock
10	8	-	1	64	NC		LV	Not connected
11	7	6	80	63	STANDBYQ	IN	OBL	Stand-by (low-active)
12	6	5	79	62	ADR_SEL	IN	OBL	I <sup>2</sup> C bus address select
13	5	4	78	61	D_CTR_I/O_0	IN/OUT	LV	D_CTR_I/O_0
14	4	3	77	60	D_CTR_I/O_1	IN/OUT	LV	D_CTR_I/O_1
15	3	-	76	59	NC		LV	Not connected
16	2	-	75	58	NC		LV	Not connected
17	-	-	-	-	NC		LV	Not connected
18	1	2	74	57	AUD_CL_OUT	OUT	LV	Audio clock output (18.432 MHz)
19	64	1	73	56	TP		LV	Test pin
20	63	52	72	55	XTAL_OUT	OUT	OBL	Crystal oscillator
21	62	51	71	54	XTAL_IN	IN	OBL	Crystal oscillator
22	61	50	70	53	TESTEN	IN	OBL	Test pin
23	60	49	69	52	ANA_IN2+	IN	AVSS via 56 pF/LV	IF Input 2 (can be left vacant, only if IF input 1 is also not in use)
24	59	48	68	51	ANA_IN-	IN	AVSS via 56 pF/LV	IF common (can be left vacant, only if IF input 1 is also not in use)
25	58	47	67	50	ANA_IN1+	IN	LV	IF input 1



26	57	46	66	49	AVSUP		OBL	Analog power supply 5V
-	-	-	65	-	AVSUP		OBL	Analog power supply 5V
-	-	-	64	-	NC		LV	Not connected
-	-	-	63	-	NC		LV	Not connected
27	56	45	62	48	AVSS		OBL	Analog ground
-	-	-	61	-	AVSS		OBL	Analog ground
28	55	44	60	47	MONO_IN	IN	LV	Mono input
-	-	-	59	-	NC		LV	Not connected
29	54	43	58	46	VREFTOP		OBL	Reference voltage IF A/D converter
30	53	42	57	45	SC1_IN_R	IN	LV	SCART 1 input, right
31	52	41	56	44	SC1_IN_L	IN	LV	SCART 1 input, left
32	51	-	55	43	ASG1		AHVSS	Analog Shield Ground 1
33	50	40	54	42	SC2_IN_R	IN	LV	SCART 2 input, right
34	49	39	53	41	SC2_IN_L	IN	LV	SCART 2 input, left
35	48	-	52	40	ASG2		AHVSS	Analog Shield Ground 2
36	47	38	51	39	SC3_IN_R	IN	LV	SCART 3 input, right
37	46	37	50	38	SC3_IN_L	IN	LV	SCART 3 input, left
38	45	-	49	37	ASG4		AHVSS	Analog Shield Ground 4
39	44	-	48	36	SC4_IN_R	IN	LV	SCART 4 input, right
40	43	-	47	35	SC4_IN_L	IN	LV	SCART 4 input, left
41	-	-	46	-	NC		LV or AHVSS	Not connected
42	42	36	45	34	AGNDC		OBL	Analog reference voltage
43	41	35	44	33	AHVSS		OBL	Analog ground
-	-	-	43	-	AHVSS		OBL	Analog ground
-	-	-	42	-	NC		LV	Not connected
-	-	-	41	-	NC		LV	Not connected
44	40	34	40	32	CAPL_M		OBL	Volume capacitor MAIN
45	39	33	39	31	AHVSUP		OBL	Analog power supply 8V
46	38	32	38	30	CAPL_A		OBL	Volume capacitor AUX
47	37	31	37	29	SC1_OUT_L	OUT	LV	SCART output 1, left
48	36	30	36	28	SC1_OUT_R	OUT	LV	SCART output 1, right
49	35	29	35	27	VREF1		OBL	Reference ground 1
50	34	28	34	26	SC2_OUT_L	OUT	LV	SCART output 2, left
51	33	27	33	25	SC2_OUT_R	OUT	LV	SCART output 2, right
52	-	-	32	-	NC		LV	Not connected
53	32	-	31	24	NC		LV	Not connected
54	31	26	30	23	DACM_SUB	OUT	LV	Subwoofer output
55	30	-	29	22	NC		LV	Not connected
56	29	25	28	21	DACM_L	OUT	LV	Loudspeaker out, left
57	28	24	27	20	DACM_R	OUT	LV	Loudspeaker out, right
58	27	23	26	19	VREF2		OBL	Reference ground 2
59	26	22	25	18	DACA_L	OUT	LV	Headphone out, left
60	25	21	24	17	DACA_R	OUT	LV	Headphone out, right
-	-	-	23	-	NC		LV	Not connected
-	-	-	22	-	NC		LV	Not connected
61	24	20	21	16	RESETQ	IN	OBL	Power-on-reset
62	23	-	20	15	NC		LV	Not connected
63	22	-	19	14	NC		LV	Not connected
64	21	19	18	13	NC		LV	Not connected
65	20	18	17	12	I2S_DA_IN2	IN	LV	I <sup>2</sup> S2-data input
66	19	17	16	11	DVSS		OBL	Digital ground
-	-	-	15	-	DVSS		OBL	Digital ground
-	-	-	14	-	DVSS		OBL	Digital ground
67	18	16	13	10	DVSUP		OBL	Digital power supply 5V
-	-	-	12	-	DVSUP		OBL	Digital power supply 5V
-	-	-	11	-	DVSUP		OBL	Digital power supply 5V
68	17	15	10	9	ADR_CL	OUT	LV	ADR clock



## 9.13. TDA1308

### 9.13.1. General Description

The TDA1308 is an integrated class AB stereo headphone driver contained in an SO8 or a DIP8 plastic package. The device is fabricated in a 1 mm CMOS process and has been primarily developed for portable digital audio applications. It gets its input from two analog audio outputs (DACA\_L and DACA\_R) of MSP 34x0G. The gain of the output is adjustable by the feedback resistor between the inputs and outputs.

### 9.13.2. Features

- Wide temperature range
- No switch ON/OFF clicks
- Excellent power supply ripple rejection
- Low power consumption
- Short-circuit resistant
- High performance
- high signal-to-noise ratio
- High slew rate
- Low distortion
- Large output voltage swing.

### 9.13.3. Pinning

SYMBOL	PIN	DESCRIPTION
OUTA	1	Output A
INA(neg)	2	Inverting input A
INA(pos)	3	Non-inverting input A
V <sub>SS</sub>	4	Negative supply
INB(pos)	5	Non-inverting input B
INB(neg)	6	Inverting input B
OUTB	7	Output B
V <sub>DD</sub>	8	Positive supply

## 9.14. PI5V330

### 9.14.1. General Description

The PI5V330 is well suited for video applications when switching composite or RGB analog. A picture-in-picture application will be described in this brief. The pixel-rate creates video overlays so two or more pictures can be viewed at the same time. An inexpensive NTSC titler can be implemented by superimposing the output of a character generator on a standard composite video background.

## 9.15. AD9883A

### 9.15.1. General Description

The AD9883A is a complete 8-bit, 140 MSPS, monolithic analog interface optimized for capturing RGB graphics signals from personal computers and workstations. Its 140 MSPS encode rate capability and full power analog bandwidth of 300 MHz supports resolutions up to SXGA (1280 × 1024 at 75 Hz).

The AD9883A includes a 140 MHz triple ADC with internal 1.25 V reference, a PLL, and programmable gain, offset, and clamp control. The user provides only a 3.3 V power supply, analog input, and Hsync and COAST signals. Three-state CMOS outputs may be powered from 2.5 V to 3.3 V.

The AD9883A's on-chip PLL generates a pixel clock from the Hsync input. Pixel clock output frequencies range from 12 MHz to 140 MHz. PLL clock jitter is 500 ps p-p typical at 140 MSPS. When the COAST signal is presented, the PLL maintains its output frequency in the absence of Hsync. A sampling phase adjustment is provided. Data, Hsync, and clock output phase relationships are maintained. The AD9883A also offers full sync processing for composite sync and sync-on-green applications. A clamp signal is generated internally or may be provided by the user through the CLAMP input pin. This interface is fully programmable via a 2-wire serial interface.

Fabricated in an advanced CMOS process, the AD9883A is provided in a space-saving 80-lead LQFP surface-mount plastic package and is specified over the -40.°C to +85.°C temperature range.

### 9.15.2. Features

- Industrial Temperature Range Operation
- 140 MSPS Maximum Conversion Rate
- 300 MHz Analog Bandwidth
- 0.5 V to 1.0 V Analog Input Range
- 500 ps p-p PLL Clock Jitter at 110 MSPS
- 3.3 V Power Supply
- Full Sync Processing
- Sync Detect for Hot Plugging
- Midscale Clamping
- Power-Down Mode
- Low Power: 500 mW Typical
- 4:2:2 Output Format Mode
- APPLICATIONS
- RGB Graphics Processing
- LCD Monitors and Projectors
- Plasma Display Panels
- Scan Converters
- Microdisplays
- Digital TV

### 9.15.3. Pin Descriptions

Complete Pinout list

Pin Type	Mnemonic	Function	Value	Pin No.
Inputs	RAIN	Analog Input for Converter R	0.0 V to 1.0 V	54
	GAIN	Analog Input for Converter G	0.0 V to 1.0 V	48
	BAIN	Analog Input for Converter B	0.0 V to 1.0 V	43
	HSYNC	Horizontal SYNC Input	3.3 V CMOS	30
	VSYN	Vertical SYNC Input	3.3 V CMOS	31
	SOGIN	Input for Sync-on-Green	0.0 V to 1.0 V	49
	CLAMP	Clamp Input (External CLAMP Signal) PLL	3.3 V CMOS	38
	COAST	COAST Signal Input	3.3 V CMOS	29
Outputs	Red [7:0]	Outputs of Converter Red, Bit 7 is the MSB	3.3 V CMOS	70–77
	Green [7:0]	Outputs of Converter Green, Bit 7 is the MSB	3.3 V CMOS	2–9
	Blue [7:0]	Outputs of Converter Blue, Bit 7 is the MSB	3.3 V CMOS	12–19
	DATAACK	Data Output Clock	3.3 V CMOS	67
	HSOUT	HSYNC Output (Phase-Aligned with DATAACK)	3.3 V CMOS	66
	VSOUT	VSYN Output (Phase-Aligned with DATAACK)	3.3 V CMOS	64
	SOGOUT	Sync-on-Green Slicer Output	3.3 V CMOS	65
References	REF BYPASS	Internal Reference Bypass	1.25 V	58
	MIDSCV	Internal Midscale Voltage Bypass		37
	FILT	Connection for External Filter Components for Internal PLL		33
Power Supply	VD	Analog Power Supply	3.3 V	39, 42, 45, 46, 51, 52, 59, 62
	VDD	Output Power Supply	3.3 V	11, 22, 23, 69, 78, 79
	PVD	PLL Power Supply	3.3 V	26, 27, 34, 35
	GND	Ground	0 V	1, 10, 20, 21, 24, 25, 28, 32, 36, 40, 41, 44, 47, 50, 53, 60, 61, 63, 68, 80
Control	SDA	Serial Port Data I/O	3.3 V CMOS	57
	SCL	Serial Port Data Clock (100 kHz Maximum)	3.3 V CMOS	56
	A0	Serial Port Address Input 1	3.3 V CMOS	55

Pin Function Descriptions:

Pin Name	Function
OUTPUTS	
HSOUT	Horizontal Sync Output A reconstructed and phase-aligned version of the Hsync input. Both the polarity and duration of this output can be programmed via serial bus registers. By maintaining alignment with DATAACK and Data, data timing with respect to horizontal sync can always be determined.
VSOUT	Vertical Sync Output A reconstructed and phase-aligned version of the video Vsync. The polarity of this output can be controlled via a serial bus bit. The placement and duration in all modes is set by the graphics transmitter.
SOGOUT	Sync-On-Green Slicer Output This pin outputs either the signal from the Sync-on-Green slicer comparator or an unprocessed but delayed version of the Hsync input. See the Sync Processing Block Diagram (Figure 12) to view how this pin is connected. (Note: Besides slicing off SOG, the output from this pin gets no other additional processing on the

	AD9883A. Vsync separation is performed via the sync separator.)
SERIAL PORT (2-WIRE) SDA SCL A0	Serial Port Data I/O Serial Port Data Clock Serial Port Address Input 1 For a full description of the 2-wire serial register and how it works, refer to the 2-Wire Serial Control Port section.
DATA OUTPUTS RED GREEN BLUE	Data Output, Red Channel Data Output, Green Channel Data Output, Blue Channel The main data outputs. Bit 7 is the MSB. The delay from pixel sampling time to output is fixed. When the sampling time is changed by adjusting the PHASE register, the output timing is shifted as well. The DATAACK and HSOUT outputs are also moved, so the timing relationship among the signals is maintained. For exact timing information, refer to Figures 7, 8, and 9.
DATA CLOCK OUTPUT DATAACK	Data Output Clock This is the main clock output signal used to strobe the output data and HSOUT into external logic. It is produced by the internal clock generator and is synchronous with the internal pixel sampling clock. When the sampling time is changed by adjusting the PHASE register, the output timing is shifted as well. The Data, DATAACK, and HSOUT outputs are all moved, so the timing relationship among the signals is maintained.
INPUTS RAIN GAIN BAIN	Analog Input for Red Channel Analog Input for Green Channel Analog Input for Blue Channel High impedance inputs that accept the Red, Green, and Blue channel graphics signals, respectively. (The three channels are identical, and can be used for any colours, but colours are assigned for convenient reference.) They accommodate input signals ranging from 0.5 V to 1.0 V full scale. Signals should be ac-coupled to these pins to support clamp operation.
HSYNC	Horizontal Sync Input This input receives a logic signal that establishes the horizontal timing reference and provides the frequency reference for pixel clock generation. The logic sense of this pin is controlled by serial register 0EH Bit 6 (Hsync Polarity). Only the leading edge of Hsync is active; the trailing edge is ignored. When Hsync Polarity = 0, the falling edge of Hsync is used. When Hsync Polarity = 1, the rising edge is active. The input includes a Schmitt trigger for noise immunity, with a nominal input threshold of 1.5 V.
VSYN	Vertical Sync Input This is the input for vertical sync.
SOGIN	Sync-on-Green Input This input is provided to assist with processing signals with embedded sync, typically on the Green channel. The pin is connected to a high speed comparator with an internally generated threshold. The threshold level can be programmed in 10 mV steps to any voltage between 10 mV and 330 mV above the negative peak of the input signal. The default voltage threshold is 150 mV. When connected to an ac-coupled graphics signal with embedded sync, it will produce a noninverting digital output on SOGOUT. (This is usually a composite sync signal, containing both vertical and horizontal sync information that must be separated before passing the horizontal sync signal to Hsync.) When not used, this input should be left unconnected. For more details on this function and how it should be configured, refer to the Sync-on-Green section.
CLAMP	External Clamp Input This logic input may be used to define the time during which the input signal is clamped to ground. It should be exercised when the reference dc level is known to be present on the analog input channels, typically during the back porch of the graphics signal. The CLAMP pin is enabled by setting control bit Clamp Function to 1, (register 0FH, Bit 7, default is 0). When disabled, this pin is ignored and the clamp timing is determined internally by counting a delay and duration from the

COAST	<p>trailing edge of the Hsync input. The logic sense of this pin is controlled by Clamp Polarity register 0FH, Bit 6. When not used, this pin must be grounded and Clamp Function programmed to 0.</p> <p>Clock Generator Coast Input (Optional) This input may be used to cause the pixel clock generator to stop synchronizing with Hsync and continue producing a clock at its current frequency and phase. This is useful when processing signals from sources that fail to produce horizontal sync pulses during the vertical interval. The COAST signal is generally <i>not</i> required for PC-generated signals. The logic sense of this pin is controlled by Coast Polarity (register 0FH, Bit 3). When not used, this pin may be grounded and Coast Polarity programmed to 1, or tied HIGH (to VD through a 10 k resistor) and Coast Polarity programmed to 0. Coast Polarity defaults to 1 at power-up.</p>
REF BYPASS	<p>Internal Reference BYPASS Bypass for the internal 1.25 V band gap reference. It should be connected to ground through a 0.1 <math>\mu</math>F capacitor. The absolute accuracy of this reference is <math>\pm 4\%</math>, and the temperature coefficient is <math>\pm 50</math> ppm, which is adequate for most AD9883A applications. If higher accuracy is required, an external reference may be employed instead.</p>
MIDSCV	<p>Midscale Voltage Reference BYPASS Bypass for the internal midscale voltage reference. It should be connected to ground through a 0.1 <math>\mu</math>F capacitor. The exact voltage varies with the gain setting of the Blue channel.</p>
FILT	<p>External Filter Connection For proper operation, the pixel clock generator PLL requires an external filter. Connect the filter shown in Figure 6 to this pin. For optimal performance, minimize noise and parasitics on this node.</p>
POWER SUPPLY VD	<p>Main Power Supply These pins supply power to the main elements of the circuit. They should be filtered and as quiet as possible.</p>
VDD	<p>Digital Output Power Supply A large number of output pins (up to 25) switching at high speed (up to 110 MHz) generates a lot of power supply transients (noise). These supply pins are identified separately from the VD pins so special care can be taken to minimize output noise transferred into the sensitive analog circuitry. If the AD9883A is interfacing with lower voltage logic, V DD may be connected to a lower supply voltage (as low as 2.5 V) for compatibility.</p>
PVD	<p>Clock Generator Power Supply The most sensitive portion of the AD9883A is the clock generation circuitry. These pins provide power to the clock PLL and help the user design for optimal performance. The designer should provide quiet, noise-free power to these pins.</p>
GND	<p>Ground The ground return for all circuitry on-chip. It is recommended that the AD9883A be assembled on a single solid ground plane, with careful attention given to ground current paths.</p>

## 9.16. SAA7118E

### 9.16.1. General Description

The SAA7118E is a video capture device for applications at the image port of VGA controllers. Philips X-VIP is a new multistandard comb filter video decoder chip with additional component processing, providing high quality, optionally scaled, video.

The SAA7118E is a combination of a four-channel analog pre-processing circuit including source selection, anti-aliasing filter and ADC, an automatic clamp and gain control, a Clock Generation Circuit (CGC), a digital multistandard decoder containing two-dimensional chrominance/luminance separation by an adaptive comb filter and a high performance scalar, including variable horizontal and vertical up and downscaling and a brightness, contrast and saturation control circuit.

It is a highly integrated circuit for desktop video and similar applications. The decoder is based on the principle of line-locked clock decoding and is able to decode the colour of PAL, SECAM and NTSC signals into ITU 601 compatible colour component values. The SAA7118E accepts CVBS or S-video (Y/C) as analog inputs from TV or VCR sources, including weak and distorted signals as well as baseband component signals Y-P<sub>B</sub> -P<sub>R</sub> or RGB. An expansion port (X-port) for digital video (bidirectional half duplex, D1 compatible) is also supported to connect to MPEG or video phone codec. At the so called image port (I-port) the SAA7118E supports 8 or 16-bit wide output data with auxiliary reference data for interfacing to VGA controllers.

The target application for the SAA7118E is to capture and scale video images, to be provided as digital video stream through the image port of a VGA controller, for capture to system memory, or just to provide digital baseband video to any picture improvement processing.

### **9.16.2. Features**

#### **Video acquisition/clock**

- Up to sixteen analog CVBS, split as desired (all of the CVBS inputs optionally can be used to convert e.g. Vestigial Side Band (VSB) signals)
- Up to eight analog Y + C inputs, split as desired
- Up to four analog component inputs, with embedded or separate sync, split as desired
- Four on-chip anti-aliasing filters in front of the Analog-to-Digital Converters (ADCs)
- Automatic Clamp Control (ACC) for CVBS, Y and C (or VSB) and component signals
- Switchable white peak control
- Four 9-bit low noise CMOS ADCs running at twice the oversampling rate (27 MHz)
- Fully programmable static gain or Automatic Gain Control (AGC), matching to the particular signal properties
- On-chip line-locked clock generation in accordance with "ITU 601"
- Requires only one crystal (32.11 or 24.576 MHz) for all standards
- Horizontal and vertical sync detection.

#### **Video decoder**

- Digital PLL for synchronization and clock generation from all standards and non-standard video sources e.g. consumer grade VTR
- Automatic detection of any supported colour standard
- Luminance and chrominance signal processing for PAL B, G, D, H, I and N, combination PAL N, PAL M, NTSC M, NTSC-Japan, NTSC 4.43 and SECAM
- Adaptive 2/4-line comb filter for two dimensional chrominance/luminance separation, also with VTR signals
  - Increased luminance and chrominance bandwidth for all PAL and NTSC standards
  - Reduced cross colour and cross luminance artefacts
- PAL delay line for correcting PAL phase errors
- Brightness Contrast Saturation (BCS) adjustment, separately for composite and baseband signals
- User programmable sharpness control
- Detection of copy-protected signals according to the macrovision standard, indicating level of protection
- Independent gain and offset adjustment for raw data path.

#### **Component video processing**

- RGB component inputs
- Y-P<sub>B</sub> -P<sub>R</sub> component inputs
- Fast blanking between CVBS and synchronous component inputs
- Digital RGB to Y-C<sub>B</sub> -C<sub>R</sub> matrix.

#### **Video scalar**

- Horizontal and vertical downscaling and up scaling to randomly sized windows
- Horizontal and vertical scaling range: variable zoom to 1/64 (icon) (note: H and V zoom are restricted by the transfer data rates)
- Anti-alias and accumulating filter for horizontal scaling
- Vertical scaling with linear phase interpolation and accumulating filter for anti-aliasing (6-bit phase accuracy)
- Horizontal phase correct up and downscaling for improved signal quality of scaled data, especially for compression and video phone applications, with 6-bit phase accuracy (1.2 ns step width)

- Two independent programming sets for scalar part, to define two 'ranges' per field or sequences over frames
- Field wise switching between decoder part and expansion port (X-port) input
- Brightness, contrast and saturation controls for scaled outputs.

#### Vertical Blanking Interval (VBI) data decoder and slicer

- Versatile VBI-data decoder, slicer, clock regeneration and byte synchronization e.g. for World Standard Teletext (WST), North-American Broadcast Text System (NABTS), close caption, Wide Screen Signalling (WSS) etc.

#### Audio clock generation

- Generation of a field-locked audio master clock to support a constant number of audio clocks per video field
- Generation of an audio serial and left/right (channel)

#### Digital I/O interfaces

- Real-time signal port (R port), inclusive continuous line-locked reference clock and real-time status information supporting RTC level 3.1 (refer to document "RTC Functional Specification" for details)
- Bidirectional expansion port (X-port) with half duplex functionality (D1), 8-bit Y-C<sub>B</sub> -C<sub>R</sub>
  - Output from decoder part, real-time and unscaled
  - Input to scalar part, e.g. video from MPEG decoder (extension to 16-bit possible)
- Video image port (I-port) configurable for 8-bit data (extension to 16-bit possible) in master mode (own clock), or slave mode (external clock), with auxiliary timing and handshake signals
- Discontinuous data streams supported
- 32-word ´ 4-byte FIFO register for video output data
- 28-word ´ 4-byte FIFO register for decoded VBI-data output
- Scaled 4 :2 :2, 4 :1 :1, 4 :2 :0, 4 :1 :0 Y-C<sub>B</sub> -C<sub>R</sub> output
- Scaled 8-bit luminance only and raw CVBS data output
- Sliced, decoded VBI-data output.

#### Miscellaneous

- Power-on control
- 5 V tolerant digital inputs and I/O ports
- Software controlled power saving standby modes supported
- Programming via serial I 2 C-bus, full read back ability by an external controller, bit rate up to 400 kbits/s
- Boundary scan test circuit complies with the "IEEE Std. 1149.b1 - 1994"
- BGA156 package.

### 9.16.3. Pinning

SYMBOL	PIN	TYPE	DESCRIPTION
XTOUT	A2	O	crystal oscillator output signal; auxiliary signal
XTALO	A3	O	24.576 MHz (32.11 MHz) crystal oscillator output; not connected if TTL clock input of XTALI is used
V <sub>SS(xtal)</sub>	A4	P	ground for crystal oscillator
TDO	A5	O	test data output for boundary scan test; note 2
XRDY	A6	O	task flag or ready signal from scaler, controlled by XRQT
XCLK	A7	I/O	clock I/O expansion port
XPD0	A8	I/O	LSB of expansion port data
XPD2	A9	I/O	MSB - 5 of expansion port data
XPD4	A10	I/O	MSB - 3 of expansion port data
XPD6	A11	I/O	MSB - 1 of expansion port data
TEST1	A12	I/pu	do not connect, reserved for future extensions and for testing: scan input
TEST2	A13	I/pu	do not connect, reserved for future extensions and for testing: scan input
AI41	B1	I	analog input 41
TEST3	B2	O	do not connect, reserved for future extensions and for testing
V <sub>DD(xtal)</sub>	B3	P	Supply voltage for crystal oscillator
XTALI	B4	I	input terminal for 24.576 MHz (32.11 MHz) crystal oscillator or connection of external oscillator with TTL compatible



			square wave clock signal
TDI	B5	I/pu	test data input for boundary scan test; note 2
TCK	B6	I/pu	test clock for boundary scan test; note 2
XDQ	B7	I/O	data qualifier for expansion port
XPD1	B8	I/O	MSB - 6 of expansion port data
XPD3	B9	I/O	MSB - 4 of expansion port data
XPD5	B10	I/O	MSB - 2 of expansion port data
XTRI	B11	I	X-port output control signal, affects all X-port pins (XPD7 to XPD0, XRH, XRV, XDQ and XCLK), enable and active polarity is under software control (bits XPE in subaddress 83H)
TEST4	B12	O	do not connect, reserved for future extensions and for testing: scan output
TEST5	B13	NC	do not connect, reserved for future extensions and for testing
TEST6	B14	NC	do not connect, reserved for future extensions and for testing
VSSA4	C1	P	ground for analog inputs AI4x
AGND	C2	P	analog ground
TEST7	C3	NC	do not connect, reserved for future extensions and for testing
TEST8	C4	NC	do not connect, reserved for future extensions and for testing
V <sub>DD1</sub>	C5	P	Digital supply voltage 1 (peripheral cells)
TRST	C6	I/pu	test reset input (active LOW), for boundary scan test (with internal pull-up); notes 2, 3 and 4
XRH	C7	I/O	horizontal reference I/O expansion port
V <sub>DD2</sub>	C8	P	Digital supply voltage 2 (core)
V <sub>DD3</sub>	C9	P	Digital supply voltage 3 (peripheral cells)
V <sub>DD4</sub>	C10	P	Digital supply voltage 4 (core)
XPD7	C11	I/O	MSB of expansion port data
TEST9	C12	NC	do not connect, reserved for future extensions and for testing
TEST10	C13	NC	do not connect, reserved for future extensions and for testing
TEST11	C14	I/pu	do not connect, reserved for future extensions and for testing: scan input
AI43	D1	I	analog input 43
AI42	D2	I	analog input 42
AI4D	D3	I	differential input for ADC channel 4 (pins AI41 to AI44)
V <sub>DDA4</sub>	D4	P	analog supply voltage for analog inputs AI4x (3.3 V)
V <sub>SS1</sub>	D5	P	Digital ground 1 (peripheral cells)
TMS	D6	I/pu	test mode select input for boundary scan test or scan test; note 2
V <sub>SS2</sub>	D7	P	Digital ground 2 (core; substrate connection)
XRV	D8	I/O	vertical reference I/O expansion port
V <sub>SS3</sub>	D9	P	Digital ground 3 (peripheral cells)
V <sub>SS4</sub>	D10	P	Digital ground 4 (core)
V <sub>SS5</sub>	D11	P	Digital ground 5 (peripheral cells)
V <sub>DD5</sub>	D12	P	Digital supply voltage 5 (peripheral cells)
TEST12	D13	I/pu	do not connect, reserved for future extensions and for testing: scan input
HPD0	D14	I/O	LSB of host port data I/O, extended C <sub>B</sub> -C <sub>R</sub> input for expansion port, extended C <sub>B</sub> -C <sub>R</sub> output for image port
AI44	E1	I	analog input 44
V <sub>DDA4A</sub>	E2	P	analog supply voltage for analog inputs AI4x (3.3 V)
AI31	E3	I	analog input 31
V <sub>SSA3</sub>	E4	P	ground for analog inputs AI3x
HPD1	E11	I/O	MSB - 6 of host port data I/O, extended C <sub>B</sub> -C <sub>R</sub> input for expansion port, extended C <sub>B</sub> -C <sub>R</sub> output for image port
HPD3	E12	I/O	MSB - 4 of host port data I/O, extended C <sub>B</sub> -C <sub>R</sub> input for expansion port, extended C <sub>B</sub> -C <sub>R</sub> output for image port
HPD2	E13	I/O	MSB - 5 of host port data I/O, extended C <sub>B</sub> -C <sub>R</sub> input for expansion port, extended C <sub>B</sub> -C <sub>R</sub> output for image port
HPD4	E14	I/O	MSB - 3 of host port data I/O, extended C <sub>B</sub> -C <sub>R</sub> input for expansion port, extended C <sub>B</sub> -C <sub>R</sub> output for image port
AI3D	F1	I/O	differential input for ADC channel 3 (pins AI31 to AI34)
AI32	F2	I	analog input 32
AI33	F3	I	analog input 33
V <sub>DDA3</sub>	F4	P	analog supply voltage for analog inputs AI3x (3.3 V)

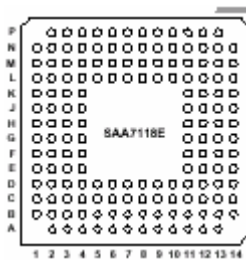
V <sub>SSD6</sub>	F11	P	Digital ground 6 (core)
V <sub>DDD6</sub>	F12	P	Digital supply voltage 6 (core)
HPD5	F13	I/O	MSB - 2 of host port data I/O, extended C <sub>B</sub> -C <sub>R</sub> input for expansion port, extended C <sub>B</sub> -C <sub>R</sub> output for image port
HPD6	F14	I/O	MSB - 1 of host port data I/O, extended C <sub>B</sub> -C <sub>R</sub> input for expansion port, extended C <sub>B</sub> -C <sub>R</sub> output for image port
AI34	G1	I	analog input 34
V <sub>DDA3A</sub>	G2	P	analog supply voltage for analog inputs AI3x (3.3 V)
AI22	G3	I	analog input 22
AI21	G4	I	analog input 21
V <sub>SSD7</sub>	G11	P	Digital ground 7 (peripheral cells)
IPD1	G12	O	MSB - 6 of image port data output
HPD7	G13	I/O	MSB of host port data I/O, extended C <sub>B</sub> -C <sub>R</sub> R input for expansion port, extended C <sub>B</sub> -C <sub>R</sub> output for image port
IPD0	G14	O	LSB of image port data output
AI2D	H1	I	differential input for ADC channel 2 (pins AI24 to AI21)
AI23	H2	I	analog input 23
V <sub>SSA2</sub>	H3	P	ground for analog inputs AI2x
V <sub>DDA2</sub>	H4	P	analog supply voltage for analog inputs AI2x
IPD2	H11	O	MSB - 5 of image port data output
V <sub>DDD7</sub>	H12	P	Digital supply voltage 7 (peripheral cells)
IPD4	H13	O	MSB - 3 of image port data output
IPD3	H14	O	MSB - 4 of image port data output
V <sub>DDA2A</sub>	J1	P	analog supply voltage for analog inputs AI2x
AI11	J2	I	analog input 11
AI24	J3	I	analog input 24
V <sub>SSA1</sub>	J4	P	ground for analog inputs AI1x
V <sub>SSD8</sub>	J11	P	Digital ground 8 (core)
V <sub>DDD8</sub>	J12	P	Digital supply voltage 8 (core)
IPD6	J13	O	MSB - 1 of image port data output
IPD5	J14	O	MSB - 2 of image port data output
AI12	K1	I	analog input 12
AI13	K2	I	analog input 13
AI1D	K3	I	differential input for ADC channel 1 (pins AI14 to AI11)
V <sub>DDA1</sub>	K4	P	analog supply voltage for analog inputs AI1x (3.3 V)
IPD7	K11	O	MSB of image port data output
IGPH	K12	O	multi purpose horizontal reference output signal; image port (controlled by subaddresses 84H and 85H)
IGP1	K13	O	general purpose output signal 1; image port (controlled by subaddresses 84H and 85H)
IGPV	K14	O	multi purpose vertical reference output signal; image port (controlled by subaddresses 84H and 85H)
V <sub>DDA1A</sub>	L1	P	analog supply voltage for analog inputs AI1x (3.3 V)
AGNDA	L2	P	analog signal ground
AI14	L3	I	analog input 14
V <sub>SSD9</sub>	L4	P	Digital ground 9 (peripheral cells)
V <sub>SSD10</sub>	L5	P	Digital ground 10 (core)
ADP6	L6	O	MSB - 2 of direct analog-to-digital converted output data (VSB)
ADP3	L7	O	MSB - 5 of direct analog-to-digital converted output data (VSB)
V <sub>SSD11</sub>	L8	P	Digital ground 11 (peripheral cells)
V <sub>SSD12</sub>	L9	P	Digital ground 12 (core)
RTCO	L10	O/st/pd	real-time control output; contains information about actual system clock frequency, field rate, odd/even sequence, decoder status, subcarrier frequency and phase and PAL sequence; the RTCO pin is enabled via I <sup>2</sup> C-bus bit RTCE; see notes 5, 6
V <sub>SSD13</sub>	L11	P	Digital ground 13 (peripheral cells)
ITRI	L12	I/(O)	image port output control signal, affects all input port pins inclusive ICLK, enable and active polarity is under software control (bits IPE in subaddress 87H); output path used for testing: scan output
IDQ	L13	O	output data qualifier for image port (optional: gated clock output)

IGP0	L14	O	general purpose output signal 0; image port (controlled by subaddresses 84H and 85H)
AOUT	M1	O	analog test output (do not connect)
V <sub>SSA0</sub>	M2	P	ground for internal Clock Generation Circuit (CGC)
V <sub>DDA0</sub>	M3	P	analog supply voltage (3.3 V) for internal clock generation circuit
V <sub>DDD9</sub>	M4	P	Digital supply voltage 9 (peripheral cells)
V <sub>DDD10</sub>	M5	P	Digital supply voltage 10 (core)
ADP7	M6	O	MSB – 1 of direct analog-to-digital converted output data (VSB)
ADP2	M7	O	MSB – 6 of direct analog-to-digital converted output data (VSB)
V <sub>DDD11</sub>	M8	P	Digital supply voltage 11 (peripheral cells)
V <sub>DDD12</sub>	M9	P	Digital supply voltage 12 (core)
RTS0	M10	O	real-time status or sync information, controlled by subaddresses 11H and 12H
V <sub>DDD13</sub>	M11	P	Digital supply voltage 13 (peripheral cells)
AMXCLK	M12	I	audio master external clock input
FSW	M13	I/pd	fast switch (blanking) with internal pull-down inserts component inputs into CVBS signal
ICLK	M14	I/O	clock output signal for image port, or optional asynchronous back-end clock input
TEST13	N1	NC	do not connect, reserved for future extensions and for testing
TEST14	N2	I/pu	do not connect, reserved for future extensions and for testing
TEST15	N3	I/pd	do not connect, reserved for future extensions and for testing
CE	N4	I/pu	chip enable or reset input (with internal pull-up)
LLC2	N5	O	line-locked 1 ÷ 2 clock output (13.5 MHz nominal)
CLKEXT	N6	I	external clock input intended for analog-to-digital conversion of VSB signals (36 MHz)
ADP5	N7	O	MSB - 3 of direct analog-to-digital converted output data (VSB)
ADP0	N8	O	LSB of direct analog-to-digital converted output data (VSB)
SCL	N9	I	serial clock input (I <sup>2</sup> C-bus)
RTS1	N10	O	real-time status or sync information, controlled by subaddresses 11H and 12H
ASCLK	N11	O	audio serial clock output
ITRDY	N12	I	target ready input for image port data
TEST16	N13	NC	do not connect, reserved for future extensions and for testing
TEST17	N14	NC	do not connect, reserved for future extensions and for testing
TEST18	P2	I/O	do not connect, reserved for future extensions and for testing
EXMCLR	P3	I/pd	external mode clear (with internal pull-down)
LLC	P4	O	line-locked system clock output (27 MHz nominal)
RES	P5	O	reset output (active LOW)
ADP8	P6	O	MSB of direct analog-to-digital converted output data (VSB)
ADP4	P7	O	MSB - 4 of direct analog-to-digital converted output data (VSB)
ADP1	P8	O	MSB - 7 of direct analog-to-digital converted output data (VSB)
INT_A	P9	O/od	I <sup>2</sup> C-bus interrupt flag (LOW if any enabled status bit has changed)
SDA	P10	I/O/od	serial data input/output (I <sup>2</sup> C-bus)
AMCLK	P11	O	audio master clock output, up to 50% of crystal clock
ALRCLK	P12	O/st/pd	audio left/right clock output; can be strapped to supply via a 3.3 kW resistor to indicate that the default 24.576 MHz crystal (ALRCLK = 0; internal pull-down) has been replaced by a 32.110 MHz crystal (ALRCLK = 1); see notes 5 and 7
TEST19	P13	I/pu	do not connect, reserved for future extensions and for testing: scan input

#### Notes

1. I = input, O = output, P = power, NC = not connected, st = strapping, pu = pull-up, pd = pull-down, od = open-drain.

2. In accordance with the "IEEE1149.1" standard the pads TDI, TMS, TCK and TRST are input pads with an internal pull-up transistor and TDO is a 3-state output pad.
3. For board design without boundary scan implementation connect the TRST pin to ground.
4. This pin provides easy initialization of the Boundary Scan Test (BST) circuit. TRST can be used to force the Test Access Port (TAP) controller to the TEST\_LOGIC\_RESET state (normal operation) at once.
5. Pin strapping is done by connecting the pin to the supply via a 3.3 kΩ resistor. During the power-up reset sequence the corresponding pins are switched to input mode to read the strapping level. For the default setting no strapping resistor is necessary (internal pull-down).
6. Pin RTCO operates as 1 2 C-bus slave address pin; RTCO = 0 slave address 42H/43H (default); RTCO = 1 slave address 40H/41H.
7. Pin ALRCLK: 0 = 24.576 MHz crystal (default; Philips order number 4322 143 05291); 1 = 32.110 MHz crystal



## 9.17. TPS72501

### 9.17.1. General Description

The TPS725xx family of 1-A low-dropout (LDO) linear regulators has fixed voltage options available that are commonly used to power the latest DSPs, FPGAs, and microcontrollers. An adjustable option ranging from 1.22 V to 5.5 V is also available. The integrated supervisory circuitry provides an active low RESET signal when the output falls out of regulation. The no capacitor/any capacitor feature allows the customer to tailor output transient performance as needed. Therefore, compared to other regulators capable of providing the same output current, this family of regulators can provide a stand alone power supply solution or a post regulator for a switch mode power supply.

These regulators are ideal for higher current applications. The family operates over a wide range of input voltages (1.8 V to 6 V) and has very low dropout (170 mV at 1-A).

Ground current is typically 210 µA at full load and drops to less than 80 µA at no load. Standby current is less than 1 µA.

Each regulator option is available in either a SOT223–5, D (TPS72501 only), or DDPAK package. With a low input voltage and properly heatsinked package, the regulator dissipates more power and achieves higher efficiencies than similar regulators requiring 2.5 V or more minimum input voltage and higher quiescent currents. These features make it a viable power supply solution for portable, battery powered equipment.

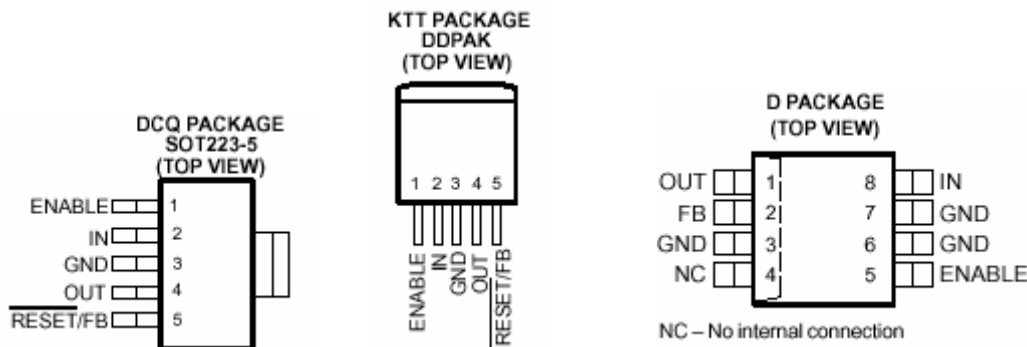
Although an output capacitor is not required for stability, transient response and output noise are improved with a 10-µF output capacitor.

Unlike some regulators that have a minimum current requirement, the TPS725 family is stable with no output load current. The low noise capability of this family, coupled with its high current operation and ease of power dissipation, make it ideal for telecom boards, modem banks, and other noise sensitive applications.

### 9.17.2. Features

- 1-A Output Current
- Available in 1.5-V, 1.6-V, 1.8-V, 2.5-V Fixed-Output and Adjustable Versions (1.2-V to 5.5-V)
- Input Voltage Down to 1.8 V
- Low 170-mV Dropout Voltage at 1 A (TPS72525)
- Stable With Any Type/Value Output Capacitor
- Integrated Supervisor (SVS) With 50-ms RESET Delay Time
- Low 210-µA Ground Current at Full Load (TPS72525)
- Less than 1-µA Standby Current

- $\pm 2\%$  Output Voltage Tolerance over Line, Load, and Temperature ( $-40^{\circ}\text{C}$  to  $125^{\circ}\text{C}$ )
- Integrated UVLO
- Thermal and Over Current Protection
- 5-Lead SOT223-5 or DPAK and 8-Pin SOP (TPS72501 only) Surface Mount Package



## 9.18. TSOP1836

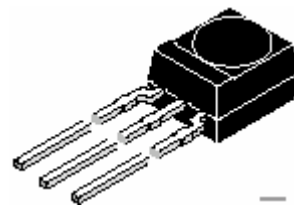
### 9.18.1. Description

The TSOP18.. – series are miniaturized receivers for infrared remote control systems. PIN diode and preamplifier are assembled on lead frame, the epoxy package is designed as IR filter. Carrier frequency for TSOP1836 is 36kHz.

The demodulated output signal can directly be decoded by a microprocessor. The main benefit is the reliable function even in disturbed ambient and the protection against uncontrolled output pulses.

### 9.18.2. Features

- Photo detector and preamplifier in one package
- Internal filter for PCM frequency
- TTL and CMOS compatibility
- Output active low
- Improved shielding against electrical field disturbance
- Suitable burst length .6 cycles/burst



### Special Features

- Small size package
- Enhanced immunity against all kinds of disturbance light
- No occurrence of disturbance pulses at the output
- Short settling time after power on ( $< 200_{\mu}\text{s}$ )

## 9.19. PCF8591

### 9.19.1. General Description

The PCF8591 is a single-chip, single-supply low power 8-bit CMOS data acquisition device with four analog inputs, one analog output and a serial  $\text{I}^2\text{C}$ -bus interface.

Three address pins A0, A1 and A2 are used for programming the hardware address, allowing the use of up to eight devices connected to the  $\text{I}^2\text{C}$ -bus without additional hardware. Address, control and data to and from the device are transferred serially via the two-line bidirectional  $\text{I}^2\text{C}$ -bus.

The functions of the device include analog input multiplexing, on-chip track and hold function, 8-bit analog-to-digital conversion and an 8-bit digital-to-analog conversion. The maximum conversion rate is given by the maximum speed of the  $\text{I}^2\text{C}$ -bus.

### 9.19.2. Features

- Single power supply
- Operating supply voltage 2.5 V to 6 V
- Low standby current

- Serial input/output via I<sup>2</sup>C-bus
- Address by 3 hardware address pins
- Sampling rate given by I<sup>2</sup>C-bus speed
- 4 analog inputs programmable as single-ended or differential inputs
- Auto-incremented channel selection
- Analog voltage range from V<sub>SS</sub> to V<sub>DD</sub>
- On-chip track and hold circuit
- 8-bit successive approximation A/D conversion
- Multiplying DAC with one analog output.

### 9.19.3. Pinning

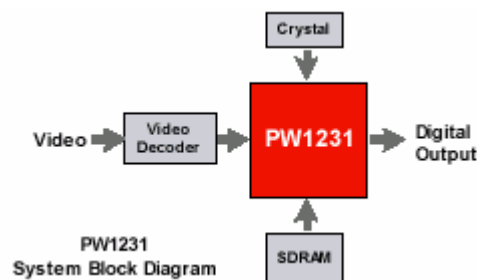
SYMBOL	PIN	DESCRIPTION
AIN0	1	analog inputs (A/D converter)
AIN1	2	
AIN2	3	
AIN3	4	
A0	5	hardware address
A1	6	
A2	7	
V <sub>SS</sub>	8	negative supply voltage
SDA	9	I <sup>2</sup> C-bus data input/output
SCL	10	I <sup>2</sup> C-bus clock input
OSC	11	oscillator input/output
EXT	12	external/internal switch for oscillator input
AGND	13	analog ground
V <sub>REF</sub>	14	voltage reference input
AOUT	15	analog output (D/A converter)
V <sub>DD</sub>	16	positive supply voltage

## 9.20. PW1231

### 9.20.1. General Description

The PW1231 is a high-quality; digital video signal processor that incorporates Pixelworks' patented deinterlacing, scaling, and video enhancement algorithms. The PW1231 accepts industry-standard video formats and resolutions, and converts the input into any desired output format. The video algorithms are highly efficient, providing excellent quality video.

The PW1231 Video Signal Processor combines many functions into a single device, including memory controller, auto-configuration, and others. This high level of integration enables simple, flexible, cost-effective solutions featuring fewer required components.



### 9.20.2. Features

- Built-In Memory Controller
- Motion-Adaptive Deinterlace Processor
- Intelligent Edge Deinterlacing
- Digital Colour/Luminance Transient Improvement (DCTI/DLTI)
- Interlaced Video Input Options, including NTSC and PAL
- Independent horizontal and vertical scaling

- Copy Protection
- Two-Wire Serial Interface

### 9.20.3. Applications

For use with Digital Displays

- Flat-Panel (LCD, DLP) TVs
- Rear Projection TVs
- Plasma Displays
- LCD Multimedia Monitors
- Multimedia Projectors

## 9.21. PW181

### 9.21.1. General Description

The PW181 Image Processor is a highly integrated “system-on-a-chip” that interfaces computer graphics and video inputs in virtually any format to a fixed-frequency flat panel display.

Computer and video images from NTSC/PAL to WUXGA at virtually any refresh rate can be resized to fit on a fixed-frequency target display device with any resolution up to WUXGA. Video data from 4:3 aspect ratio NTSC or PAL and 16:9 aspect ratio HDTV or SDTV is supported. Multi-region, nonlinear scaling allows these inputs to be resized optimally for the native resolution of the display.

Advanced scaling techniques are supported, such as format conversion using multiple programmable regions. Three independent image scalars coupled with frame locking circuitry and dual programmable colour lookup tables create sharp images in multiple windows, without user intervention.

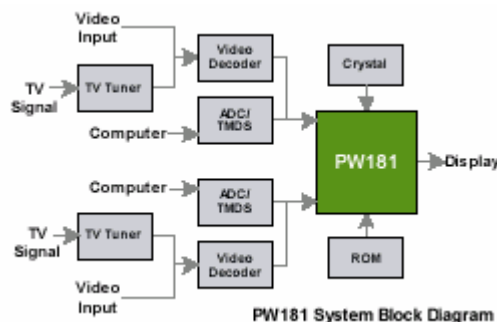
Embedded SDRAM frame buffers and memory controllers perform frame rate conversion and enhanced video processing completely on-chip. A separate memory is dedicated to storage of on-screen display images and CPU general purpose use.

Advanced video processing techniques are supported using the internal frame buffer, including motion adaptive, temporal deinterlacing with film mode detection. When used in combination with the new third-generation scalar, this advanced video processing technology delivers the highest quality video for advanced displays.

Both input ports support integrated DVI 1.0 content protection using standard DVI receivers.

A new advanced OSD Generator with more colours and larger sizes supports more demanding OSD applications, such as on-screen programming guides. When coupled with the new, faster, integrated microprocessor, this OSD Generator supports advanced OSD animation techniques.

Programmable features include the user interface, custom start-up screen, all automatic imaging features, and special screen effects.



### 9.21.2. Features

- Third-generation, two-dimensional filtering techniques
- Third-generation, advanced scaling techniques
- Second-generation Automatic Image Optimization
- Frame rate conversion
- Video processing
- On-Screen Display (OSD)
- On-chip microprocessor
- JTAG debugger and boundary scan
- Picture-in-picture (PIP)

- Multi-region, non-linear scaling
- Hardware 2-wire serial bus support

### **9.21.3. Applications**

- Multimedia Displays
- Plasma Displays
- Digital Television

## **9.22. SIL151B**

### **9.22.1. General Description**

The Sil 151B receiver uses Panel Link Digital technology to support high-resolution displays up to SXGA (25-112MHz). This receiver supports up to true colour panels (24 bit/pixel, 16M colours) with both one and two pixels per clock.

All Panel Link products are designed on a scaleable CMOS architecture, ensuring support for future performance enhancements while maintaining the same logical interface. System designers can be assured that the interface will be stable through a number of technology and performance generations. Panel Link Digital technology simplifies PC and display interface design by resolving many of the system level issues associated with high-speed mixed signal design, providing the system designer with a digital interface solution that is quicker to market and lower in cost.

### **9.22.2. Features**

- Low Power Operation: 201mA max. current consumption at 3.3V core operation
- Time staggered data output for reduced ground bounce and lower EMI
- Sync Detect feature for Plug & Display iMHot Plugging
- Cable Distance Support: over 5m with twisted-pair, fiber-optics ready
- Compliant with DVI 1.0 (DVI is backwards compatible with VESA ® P&D™ and DFP)
- HSYNC de-jitter circuitry enables stable operation even when HSYNC contains jitter
- Low power standby mode
- Automatic entry into standby mode with clock detect circuitry
- Standard and Pb-free packages

## **9.23. SDRAM 4M x 16 (MT48LC4M16A2TG-75)**

### **9.23.1. General Description**

The Micron ® 64Mb SDRAM is a high-speed CMOS, dynamic random-access memory containing 67,108,864 bits. It is internally configured as a quad-bank DRAM with a synchronous interface (all signals are registered on the positive edge of the clock signal, CLK). Each of the x4's 16,777,216-bit banks is organized as 4,096 rows by 1,024 columns by 4 bits. Each of the x8's 16,777,216-bit banks is organized as 4,096 rows by 512 columns by 8 bits. Each of the x16's 16,777,216-bit banks is organized as 4,096 rows by 256 columns by 16 bits.

Read and write accesses to the SDRAM are burst oriented; accesses start at a selected location and continue for a programmed number of locations in a programmed sequence. Accesses begin with the registration of an ACTIVE command, which is then followed by a READ or WRITE command. The address bits registered coincident with the ACTIVE command are used to select the bank and row to be accessed (BA0, BA1 select the bank; A0-A11 select the row). The address bits registered coincident with the READ or WRITE command are used to select the starting column location for the burst access. The SDRAM provides for programmable READ or WRITE burst lengths of 1, 2, 4, or 8 locations, or the full page, with a burst terminate option. An auto precharge function may be enabled to provide a self-timed row precharge that is initiated at the end of the burst sequence.

The 64Mb SDRAM uses an internal pipelined architecture to achieve high-speed operation. This architecture is compatible with the 2n rule of prefetch architectures, but it also allows the column address to be changed on every clock cycle to achieve a high-speed, fully random access. Precharging one bank while accessing one of the other three banks will hide the precharge cycles and provide seamless, high-speed, random-access operation.

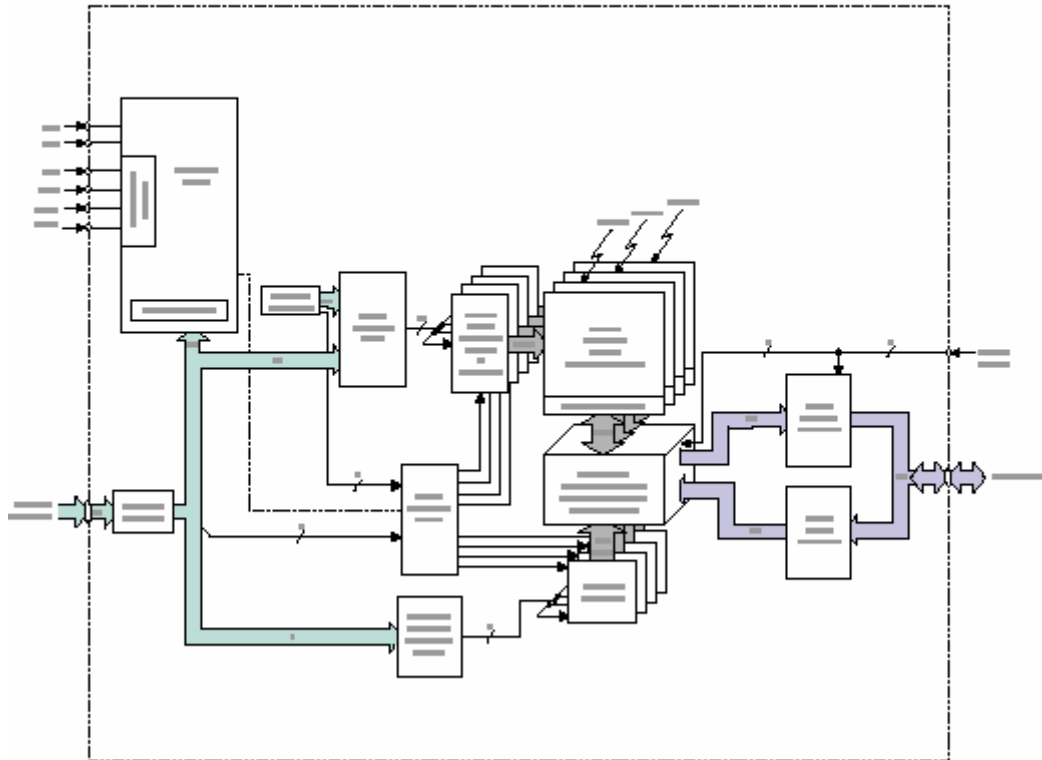
The 64Mb SDRAM is designed to operate in 3.3V memory systems. An auto refresh mode is provided, along with a power-saving, power-down mode. All inputs and outputs are LVTTTL-compatible.



SDRAMs offer substantial advances in DRAM operating performance, including the ability to synchronously burst data at a high data rate with automatic column-address generation, the ability to interleave between internal banks in order to hide precharge time and the capability to randomly change column addresses on each clock cycle during a burst access.

#### FUNCTIONAL BLOCK DIAGRAM

4 Meg x 16 SDRAM



#### 9.23.2. Features

- PC66-, PC100-, and PC133-compliant
- Fully synchronous; all signals registered on positive edge of system clock
- Internal pipelined operation; column address can be changed every clock cycle
- Internal banks for hiding row access/precharge
- Programmable burst lengths: 1, 2, 4, 8, or full page
- Auto Precharge, includes CONCURRENT AUTO PRECHARGE, and Auto Refresh Modes
- Self Refresh Modes: standard and low power
- 64ms, 4,096-cycle refresh
- LVTTTL-compatible inputs and outputs
- Single +3.3V  $\pm 0.3V$  power supply

#### 9.23.3. Pin Descriptions

PIN NUMBERS	SYMBOL	TYPE	DESCRIPTION
38	CLK	Input	Clock: CLK is driven by the system clock. All SDRAM input signals are sampled on the positive edge of CLK. CLK also increments the internal burst counter and controls the output registers.
37	CKE	Input	Clock Enable: CKE activates (HIGH) and deactivates (LOW) the CLK signal. Deactivating the clock provides PRECHARGE POWER-DOWN and SELF REFRESH operation (all banks idle), ACTIVE POWER-DOWN (row active in any bank) or CLOCK SUSPEND operation (burst/access in progress). CKE is synchronous except after the device enters power-down and self refresh modes, where CKE becomes asynchronous until

			after exiting the same mode. The input buffers, including CLK, are disabled during power-down and self refresh modes, providing low standby power. CKE may be tied HIGH.
19	CS#	Input	Chip Select: CS# enables (registered LOW) and disables (registered HIGH) the command decoder. All commands are masked when CS# is registered HIGH. CS# provides for external bank selection on systems with multiple banks. CS# is considered part of the command code.
16, 17, 18	WE#, CAS#, RAS#	Input	Command Inputs: WE#, CAS#, and RAS# (along with CS#) define the command being entered.
39	x4, x8: DQM	Input	Input/Output Mask: DQM is an input mask signal for write accesses and an output enable signal for read accesses. Input data is masked when DQM is sampled HIGH during a WRITE cycle. The output buffers are placed in a High-Z state (two-clock latency) when DQM is sampled HIGH during a READ cycle. On the x4 and x8, DQML (Pin 15) is a NC and DQMH is DQM. On the x16, DQML corresponds to DQ0-DQ7 and DQMH corresponds to DQ8-DQ15. DQML and DQMH are considered same state when referenced as DQM.
15, 39	x16: DQML, DQMH		
20, 21	BA0, BA1	Input	Bank Address Inputs: BA0 and BA1 define to which bank the ACTIVE, READ, WRITE or PRECHARGE command is being applied.
23-26, 29-34, 22, 35	A0-A11	Input	Address Inputs: A0-A11 are sampled during the ACTIVE command (row-address A0-A11) and READ/WRITE command (column-address A0-A9 [x4]; A0-A8 [x8]; A0-A7 [x16]; with A10 defining auto precharge) to select one location out of the memory array in the respective bank. A10 is sampled during a PRECHARGE command to determine if all banks are to be precharged (A10[HIGH]) or bank selected by BA0, BA1 (A1[LOW]). The address inputs also provide the op-code during a LOAD MODE REGISTER command.
2, 4, 5, 7, 8, 10, 11, 13, 42, 44, 45, 47, 48, 50, 51, 53	DQ0-DQ15	x16: I/O	Data Input/Output: Data bus for x16 (4, 7, 10, 13, 42, 45, 48, and 51 are NCs for x8; and 2, 4, 7, 8, 10, 13, 42, 45, 47, 48, 51, and 53 are NCs for x4).
2, 5, 8, 11, 44, 47, 50, 53	DQ0-DQ7	x8: I/O	Data Input/Output: Data bus for x8 (2, 8, 47, 53 are NCs for x4).
5, 11, 44, 50	DQ0-DQ3	x4: I/O	Data Input/Output: Data bus for x4.
40	NC	–	No Connect: These pins should be left unconnected.
36	NC	–	Address input (A12) for the 256Mb and 512Mb devices
3, 9, 43, 49	V <sub>DD</sub> Q	Supply	DQ Power: Isolated DQ power on the die for improved noise immunity.
6, 12, 46, 52	V <sub>SS</sub> Q	Supply	DQ Ground: Isolated DQ ground on the die for improved noise immunity.
1, 14, 27	V <sub>DD</sub>	Supply	Power Supply: +3.3V ±0.3V.
28, 41, 54	V <sub>SS</sub>	Supply	Ground.

## **9.24. FLASH 8MBit**

### **9.24.1. Description**

The M29W800A is a non-volatile memory that may be erased electrically at the block or chip level and programmed in-system on a Byte-by-Byte or Word-by-Word basis using only a single 2.7V to 3.6V  $V_{CC}$  supply. For Program and Erase operations the necessary high voltages are generated internally. The device can also be programmed in standard programmers.

The array matrix organization allows each block to be erased and reprogrammed without affecting other blocks. Blocks can be protected against programming and erase on programming equipment, and temporarily unprotected to make changes in the application. Each block can be programmed and erased over 100,000 cycles.




Instructions for Read/Reset, Auto Select for reading the Electronic Signature or Block Protection status, Programming, Block and Chip Erase, Erase Suspend and Resume are written to the device in cycles of commands to a Command Interface using standard microprocessor write timings.

### **9.24.2. Features**

- 2.7V to 3.6V Supply Voltage for Program, Erase and Read Operations
- Access Time: 80ns
- Programming Time: 10 $\mu$ s typical
- Program/Erase Controller (P/E.C.)
  - Program Byte-by-Byte or Word-by-Word
  - Status Register bits and Ready/Busy Output
- Security Protection Memory Area
- Instruction Address Coding: 3 Digits
- Memory Blocks
  - Boot Block (Top or Bottom location)
  - Parameter and Main blocks
- Block, Multi-Block and Chip Erase
- Multi Block Protection/Temporary Unprotection Modes
- Erase Suspend and Resume Modes
  - Read and Program another Block during Erase Suspend
- Low Power Consumption
  - Stand-by and Automatic Stand-by
- 100,000 Program/Erase Cycles per Block
- 20 Years Data Retention
  - Defectivity below 1ppm/year
- Electronic Signature
  - Manufacturer Code: 20h
  - Top Device Code, M29W800AT: D7h
  - Bottom Device Code, M29W800AB: 5Bh

## 10. SERVICE MENU SETTINGS

All system, geometry and white balance alignments are performed in production service mode. Before starting the production mode alignments, make sure that all manual adjustments are done correctly. To start production mode alignments enter the MENU by pressing “M” button and then press the buttons Mute, Dual, Wide and Red respectively. The following menu appears on the screen.




				
display				
blank color	black	red	green	blue
panel	0 852x480			
power on time	33:5			
backlight on time	33:0			
Vestel V1.0.10 Release Build				
scart prescale				25
nicam prescale				32

down to change display settings

There are 3 submenus in service menu. These are **display**, **calibration** and **deinterlacer** menus. Press “◀/▶” buttons to select a menu title and then “▲/▼” buttons to select a menu item and “◀/▶” or “OK” buttons to set the menu item to the desired option. To exit the service menu press “M” button. Entire service menu parameters of Plasma TV are listed below.

### 10.1. display menu

By pressing “◀/▶” buttons select the first icon. **display** menu appears on the screen.

				
display				
blank color	black	red	green	blue
panel	0 852x480			
power on time	33:5			
backlight on time	33:0			
Vestel V1.0.10 Release Build				
scart prescale				25
nicam prescale				32

down to change display settings

#### blank colour

By pressing “▲/▼” button, select **blank colour**. Press “◀/▶” button to set the blank colour. The options are: **black**, **red**, **green** and **blue**.

#### panel

Displays panel resolution

#### power on time

Displays total working time of the set

#### backlight on time

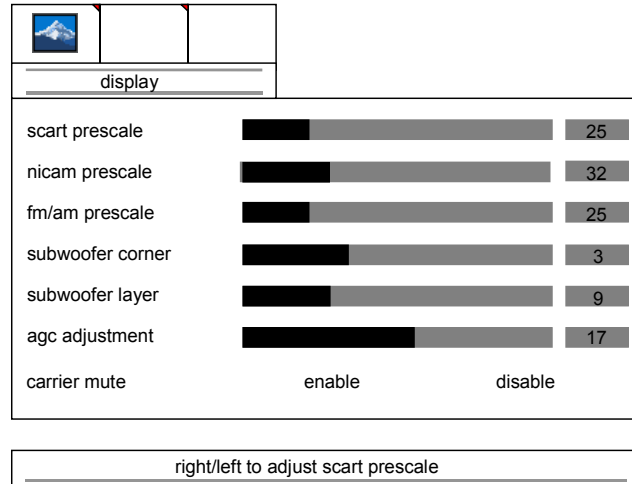
Displays total backlight on time of the set. (Not used for plasma displays)

### scart prescale

By pressing "▲/▼" button, select **scart prescaler**. Press "◀/▶" button to set the scart prescaler. Scart prescale can be adjusted between 0 and 127.

### nicam prescale

By pressing "▲/▼" button, select **nicam prescaler**. Press "◀/▶" button to set the nicam prescaler. Nicam prescale can be adjusted between 0 and 127.



### fm/am prescale

By pressing "▲/▼" button, select **fm/am prescaler**. Press "◀/▶" button to set the fm/am prescaler. Fm/am prescale can be adjusted between 0 and 127.

### subwoofer corner

By pressing "▲/▼" button, select **subwoofer corner**. Press "◀/▶" button to set the subwoofer corner. Subwoofer corner can be adjusted between 0 and 7.

### subwoofer level

By pressing "▲/▼" button, select **subwoofer level**. Press "◀/▶" button to set the subwoofer level. Subwoofer level can be adjusted between 0 and 32.

### agc adjustment

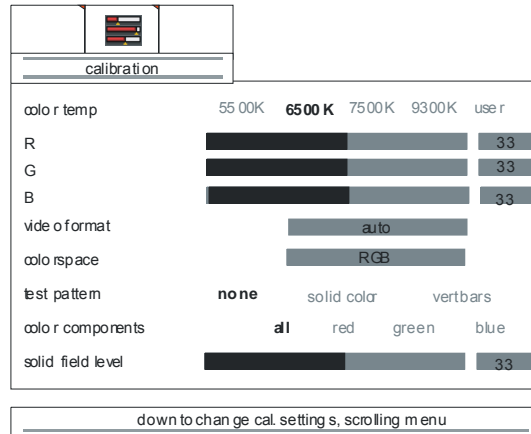
Adjustment for automatic gain control of tuner. By pressing "▲/▼" button, select **agc adjustment**. Press "◀/▶" button to set the agc adjustment. Agc adjustment can be adjusted between 0 and 31.

### carrier mute

This option is not available for this model.

## 10.2. calibration menu

By pressing “◀/▶” buttons select the second icon. **calibration** menu appears on the screen.



### colour temp

By pressing “▲/▼” button, select **colour temp**. Press “◀/▶” button to set the colour temperature. The options are: **5500K, 6500K, 7500K, 9300K** and **user**.

### R/G/B

By pressing “▲/▼” button, select **Red, Green or Blue**. Press “▶” button to increase the colour temperature. Press “◀” button to decrease the colour temperature. Colour temperature can be adjusted between values 0 and 63.

### video format

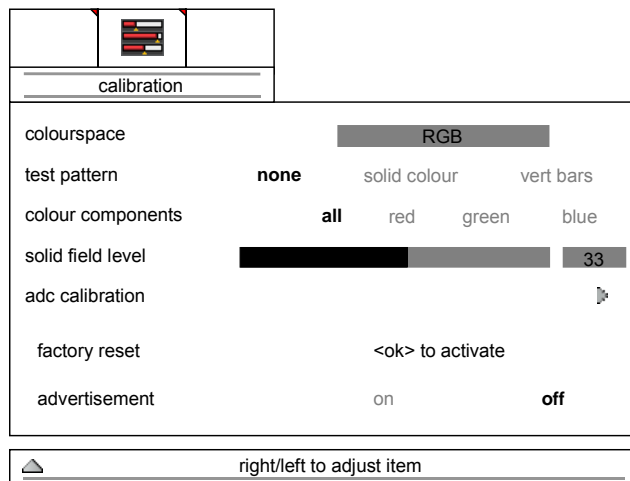
By pressing “▲/▼” button, select **video format**. Press “◀/▶” button to set the video format. The options are: **auto, ntsc, pal, secam** and **ntsc japan**.

### colour space

Displays the current colour space used. **RGB, YPbPr SMPTE240, YPbPr REC709** and **YCbCr REC601**.

### test pattern

By pressing “▲/▼” button, select **test pattern**. Press “◀/▶” button to set the test pattern. The options are: **none, solid colour** and **vert bars**.



### colour components

By pressing "▲/▼" button, select **colour components**. Press "◀/▶" button to set the colour components. The options are: **all**, **red**, **green** and **blue**.

### solid field level

By pressing "▲/▼" button, select **solid field level**. Press "▶" button to increase or "◀" button to decrease the solid field level. Solid field level can be adjusted between 0 and 64.

### adc calibration

Not used for this model.

### factory reset

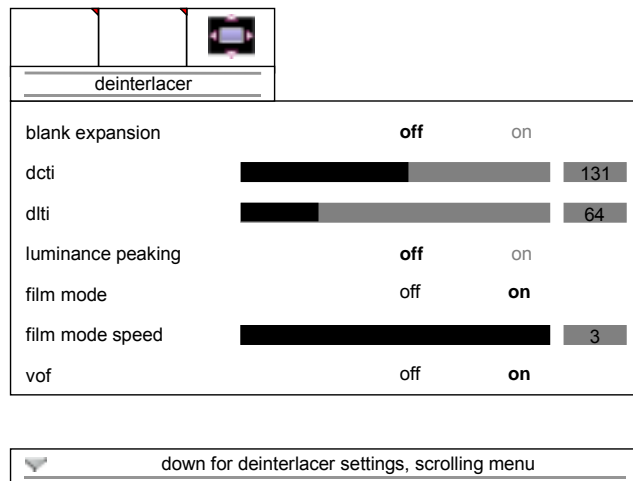
By pressing "▲/▼" button, select **factory reset**. Press "OK" button to return to the factory setting values.

### advertisement

When this item is made **on**, VESTEL advertisement is represented at certain time intervals.

### deinterlacer menu

By pressing "◀/▶" buttons select the third icon. **deinterlacer** menu appears on the screen.



### blank expansion

By pressing "▲/▼" button, select **blank expansion**. **blank expansion** can be set to **on** or **off** by pressing "◀/▶" button.

### dcti

Digital colour transition improvement: By pressing "▲/▼" button, select **dcti**. DCTI can be adjusted between **0** and **255** by pressing "◀/▶" button.

### dlتي

Digital luma transition improvement: By pressing "▲/▼" button, select **dlتي**. DLTI can be adjusted between **0** and **255** by pressing "◀/▶" button.

### luminance peaking

By pressing "▲/▼" button, select **luminance peaking**. Luminance peaking can be set to **on** or **off** by pressing "◀/▶" button.

### film mode

By pressing "▲/▼" button, select **film mode**. Film mode speed can be set to **on** or **off** by pressing "◀/▶" button.

deinterlacer		
vof	off	on
bad cut	off	on
nr threshold	low	high
noise reduction	<div><div></div></div>	40
lai level	<div><div></div></div>	2
sharpness	<div><div></div></div>	10
sparkle	<div><div></div></div>	255

right/left to adjust item

### film mode speed

By pressing "▲/▼" button, select **film mode speed**. Film mode speed can be set to **0**, **1**, **2** or **3** by pressing "◀/▶" button.

### vof

video on film. By pressing "▲/▼" button, select **vof**. VOF can be set to **on** or **off** by pressing "◀/▶" button.

### bad cut

By pressing "▲/▼" button, select **bad cut**. Bad cut can be set to **on** or **off** by pressing "◀/▶" button.

### nr threshold

By pressing "▲/▼" button, select **nr threshold**. Nr threshold can be set to **low** or **high** by pressing "◀/▶" button.

### noise reduction

By pressing "▲/▼" button, select **noise reduction**. Noise reduction can be adjusted between **0** and **255** by pressing "◀/▶" button.

### lai level

By pressing "▲/▼" button, select **lai level**. Lai level can be set to **0**, **1** or **2** by pressing "◀/▶" button.

### sharpness

By pressing "▲/▼" button, select **sharpness**. Sharpness can be adjusted between **0** and **255** by pressing "◀/▶" button.

### sparkle

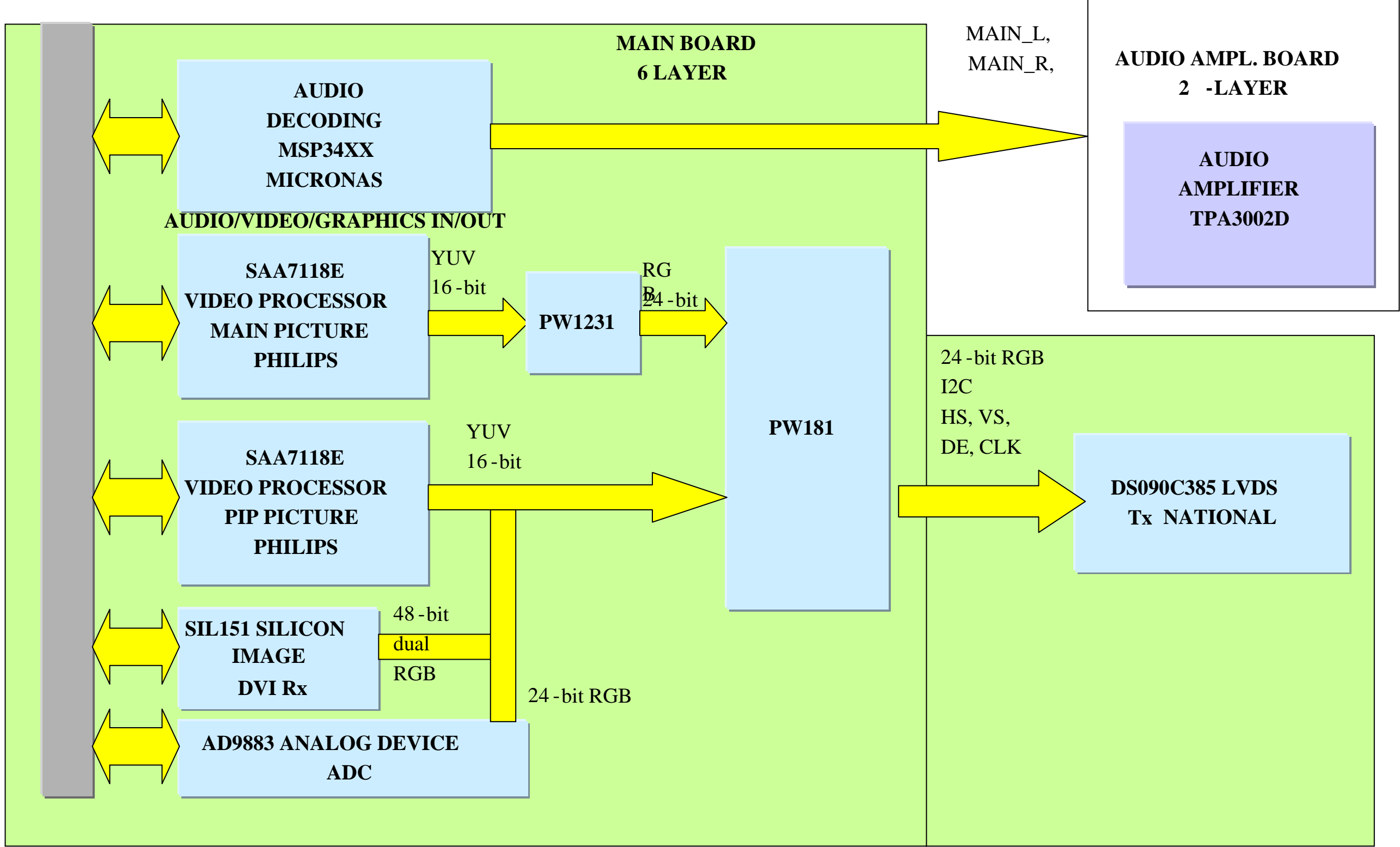
By pressing "▲/▼" button, select **sparkle**. Sparkle can be adjusted between **0** and **255** by pressing "◀/▶" button.



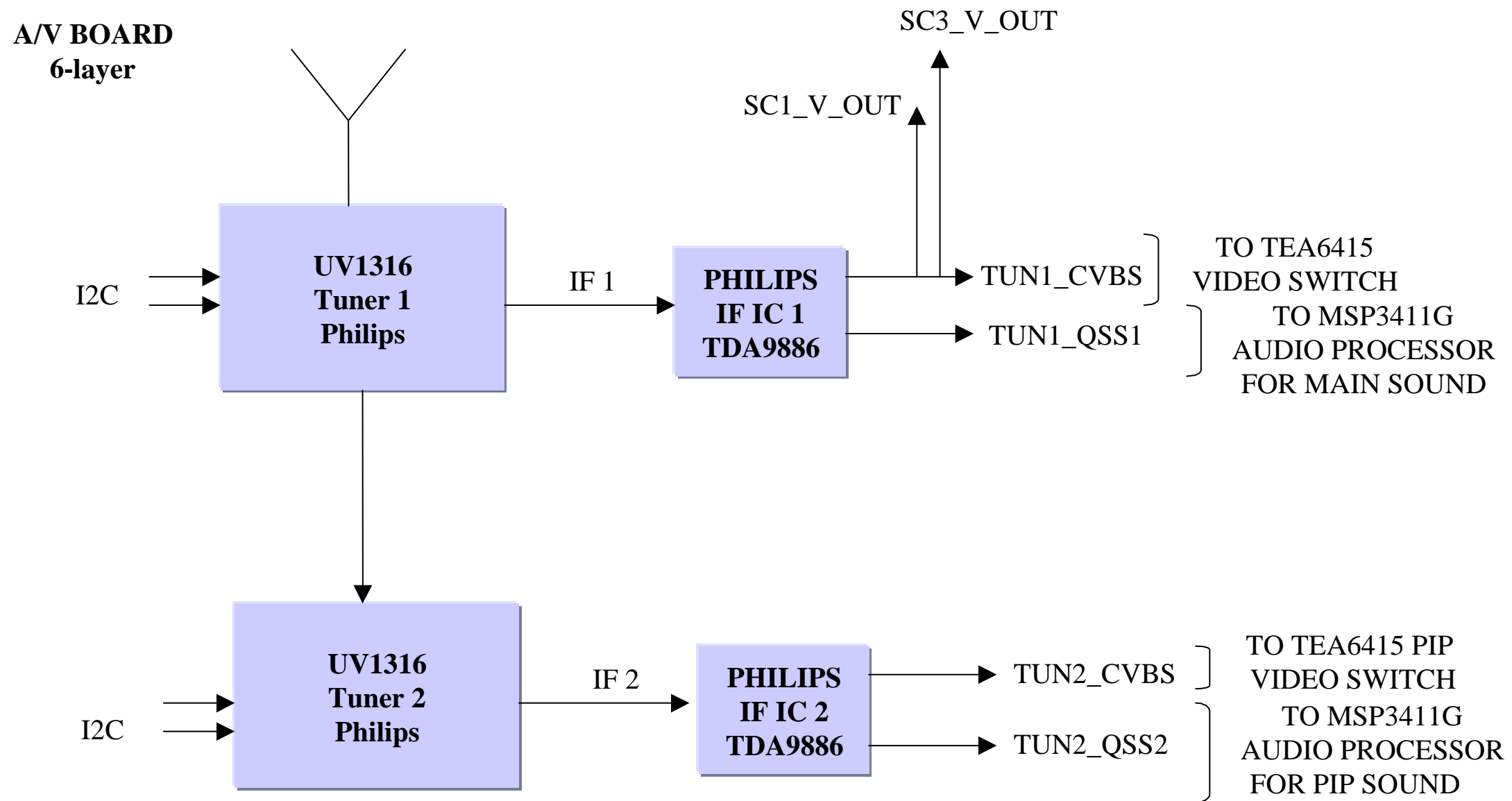
### 10.3. Service menu factory reset values

	SERVICE MENU	
DISPLAY	BLANK COLOUR	black
	SCART PRESCALE	15
	NICAM PRESCALE	32
	FM/AM PRESCALE	14
	SUBWOOFER CORNER	5
	SUBWOOFER LEVEL	32
	AGC	16
CALIBRATION	COLOUR TEMPERATURE	6500
	COLOUR TEMPERATURE-USER	6500
	VIDEO FORMAT	AUTO
	COLOUR SPACE	autodetected
	TEST PATTERN	none
	COLOUR COMPONENTS	all
	SOLID FIELD LEVEL	33
DEINTERLACER	INITIAL APS	on
	BLACK EXPANSION	These values are not recorded, for this reason they are adjusted to a specified value.
	DCTI	
	DLTI	
	LUMINANCE PEAKING	
	FILM MODE	
	FILM MODE SPEED	
	VOF	
	BAD CUT	
	NR THRESHOLD	
	NOISE REDUCTION	
	LAI LEVEL	
	SHARPNESS	
	SPARKLE	

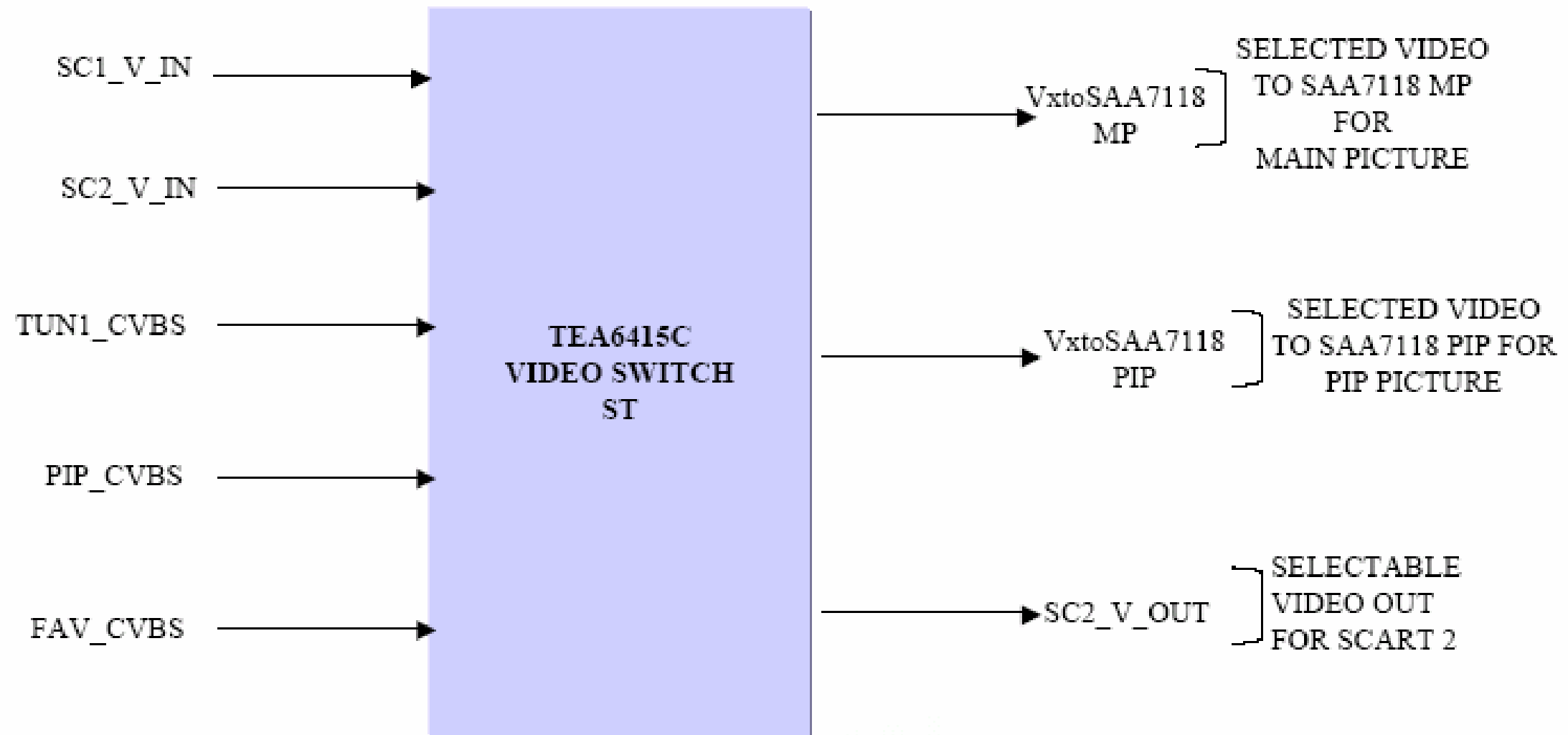
GENERAL BLOCK DIAGRAM



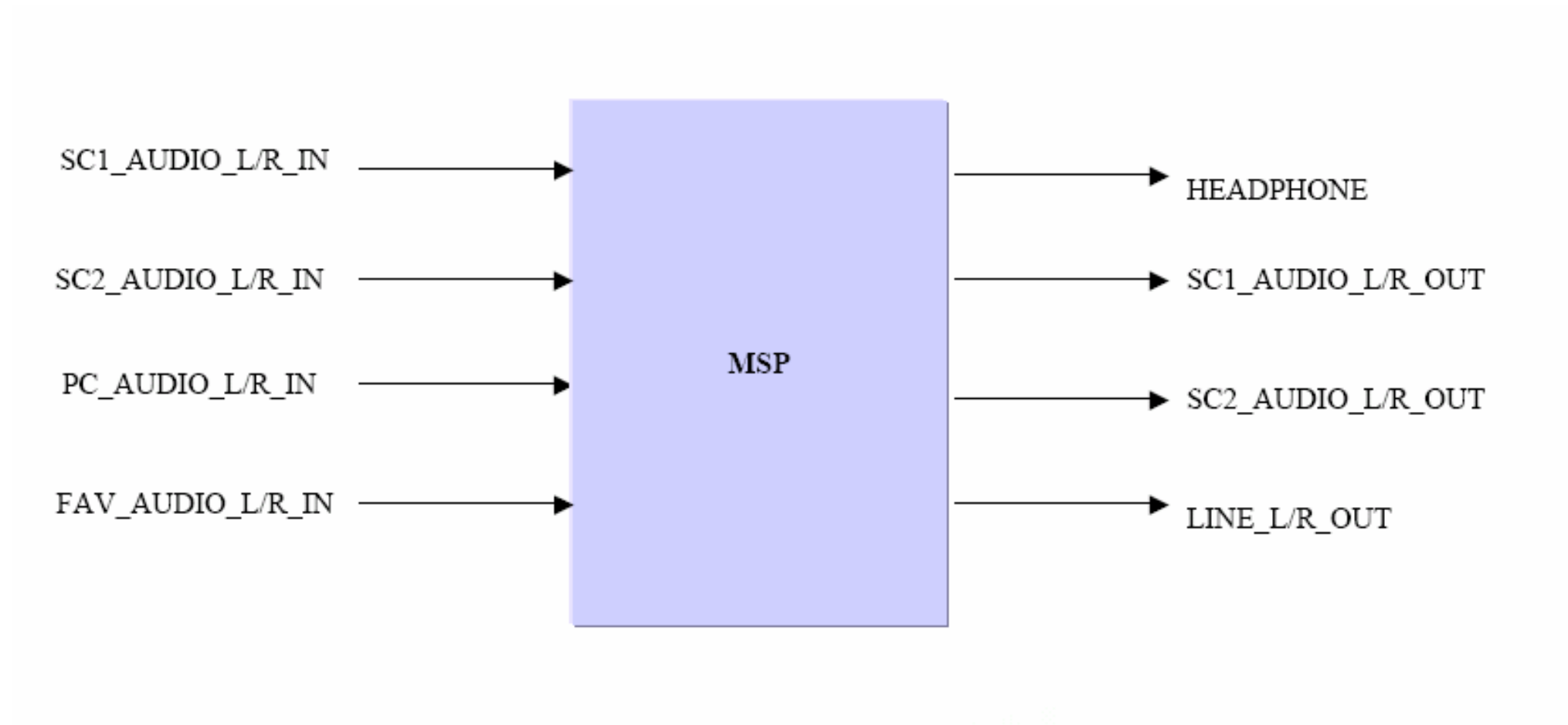
# TUNER&IF BLOCK



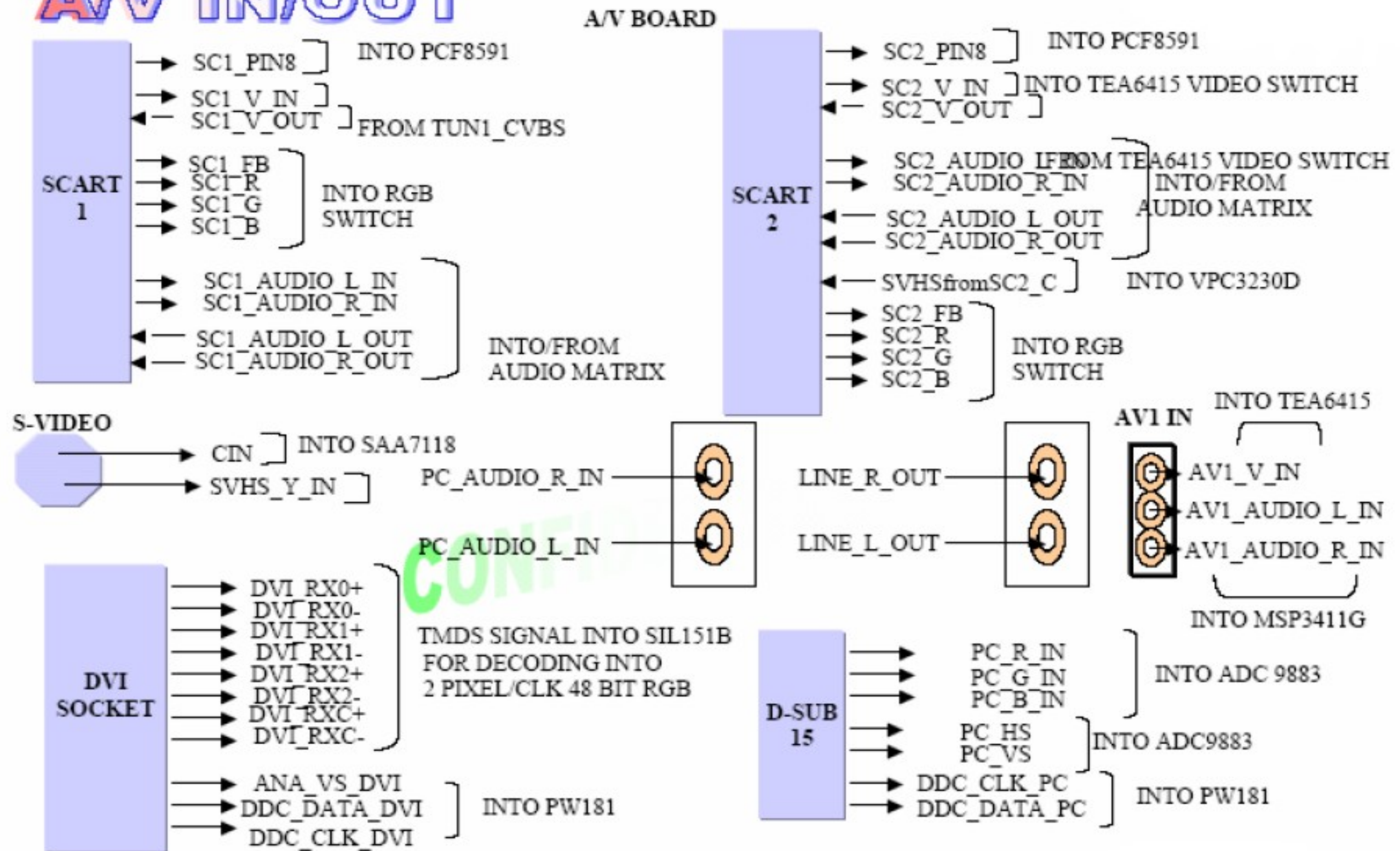
## VIDEO MATRIXING



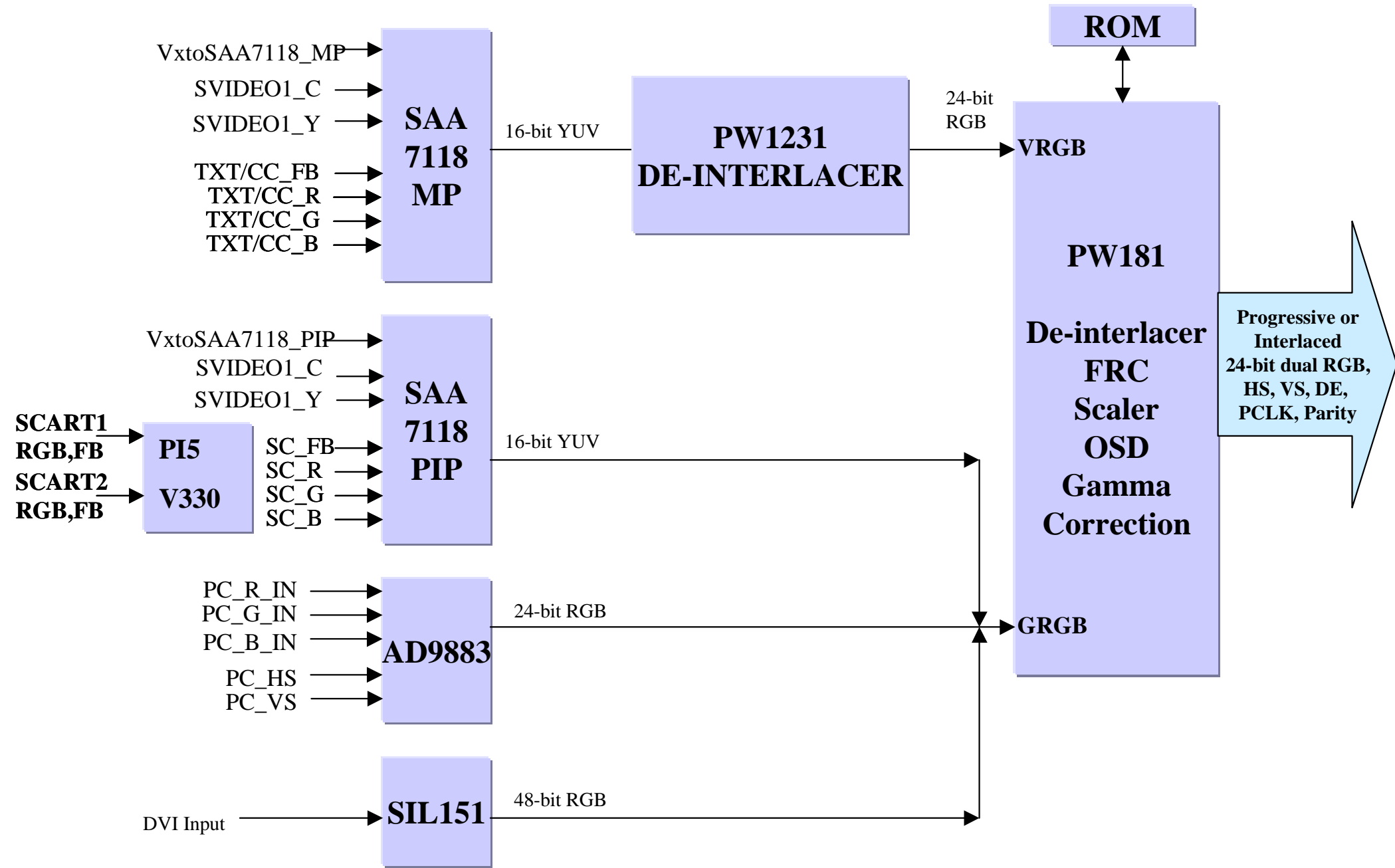
## AUDIO MATRIXING



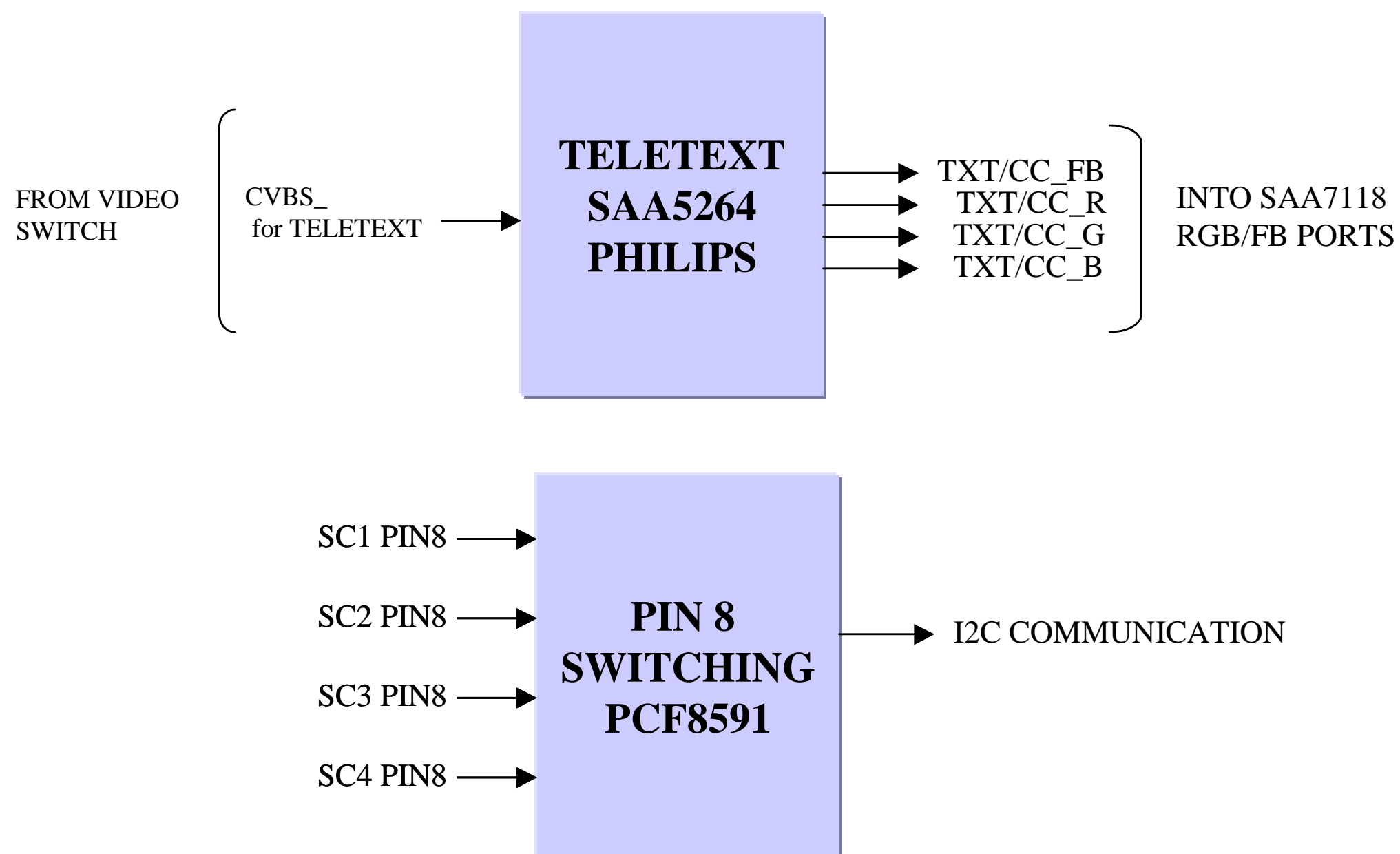
# AV IN/OUT



# VIDEO & IMAGE PROCESSING



# TELETEXT DECODING & PIN8 SWITCHING





# INPUT & OUTPUTS

**1. SCART 1 CVBS INPUT**

**2. SCART 2 CVBS INPUT**

**3. SCART 1 RGB FB INPUT**

**4. SCART 2 RGB FB INPUT**

**5. FAV IN**

**6. FRONT SVHS IN**

**7. VGA INPUT**

**8. DVI INPUT**

**9. PC AUDIO INPUT**

**10. MAIN TUNER**

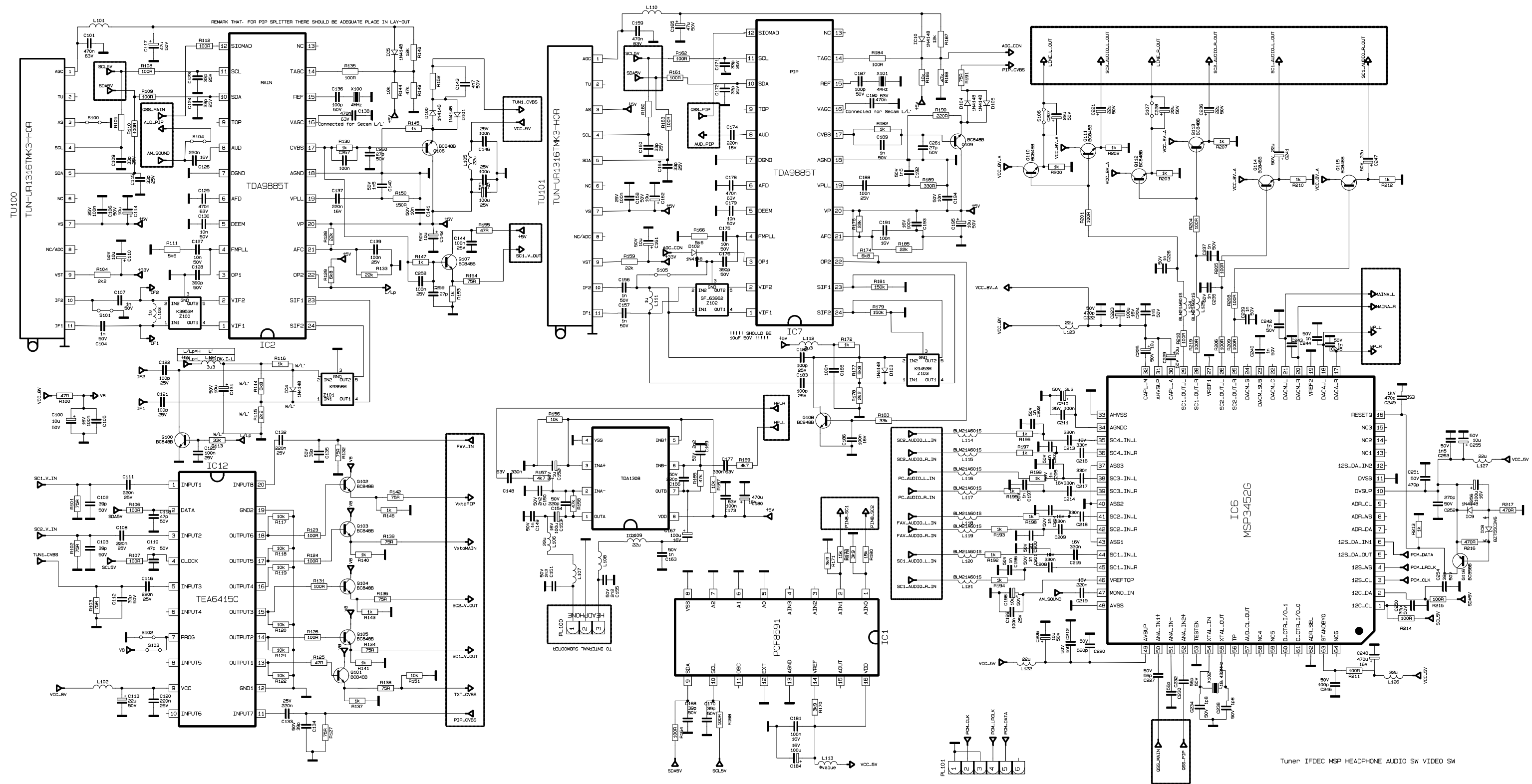
**11. PIP TUNER**

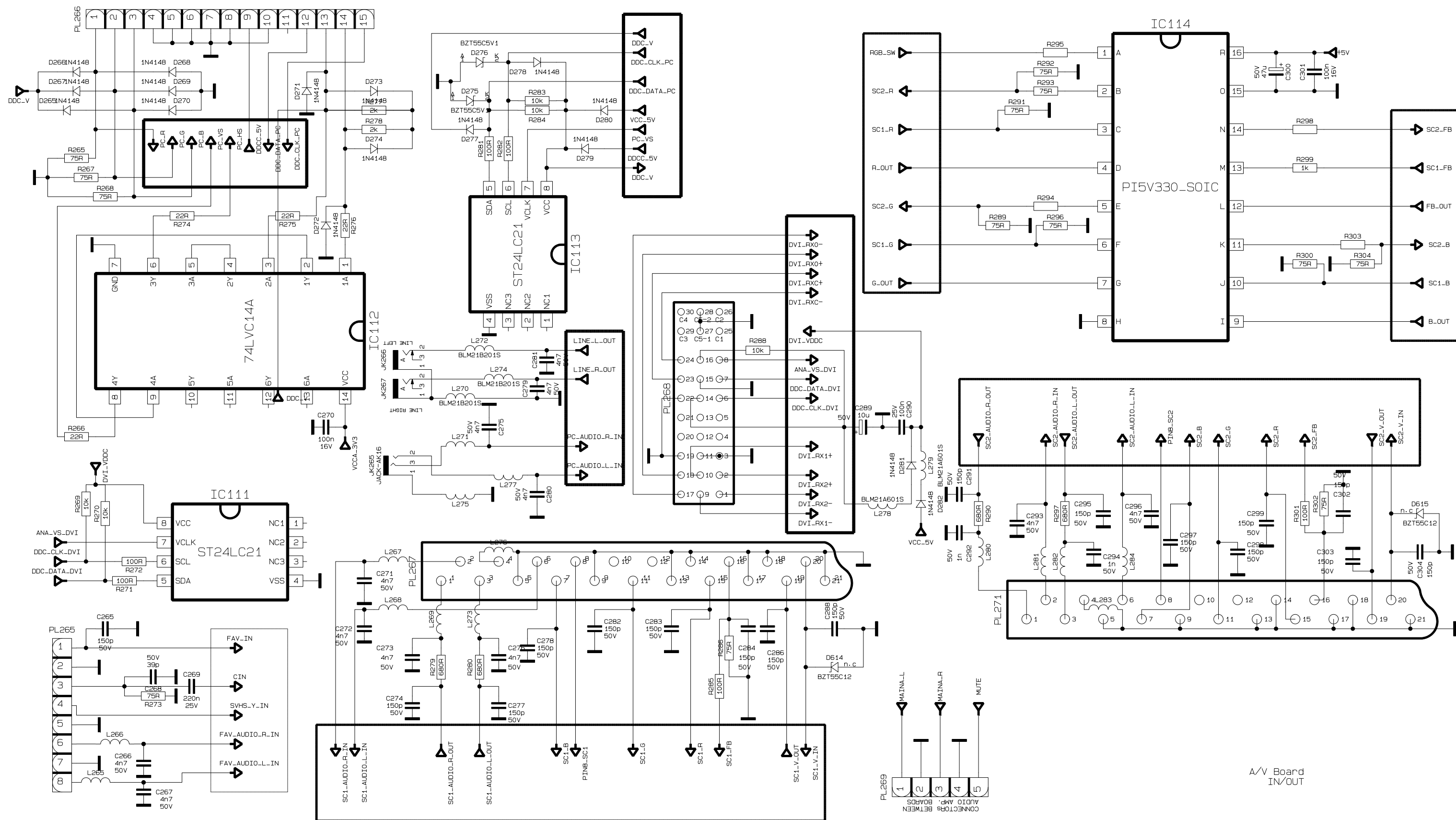
**1. SCART 1 CVBS OUT**

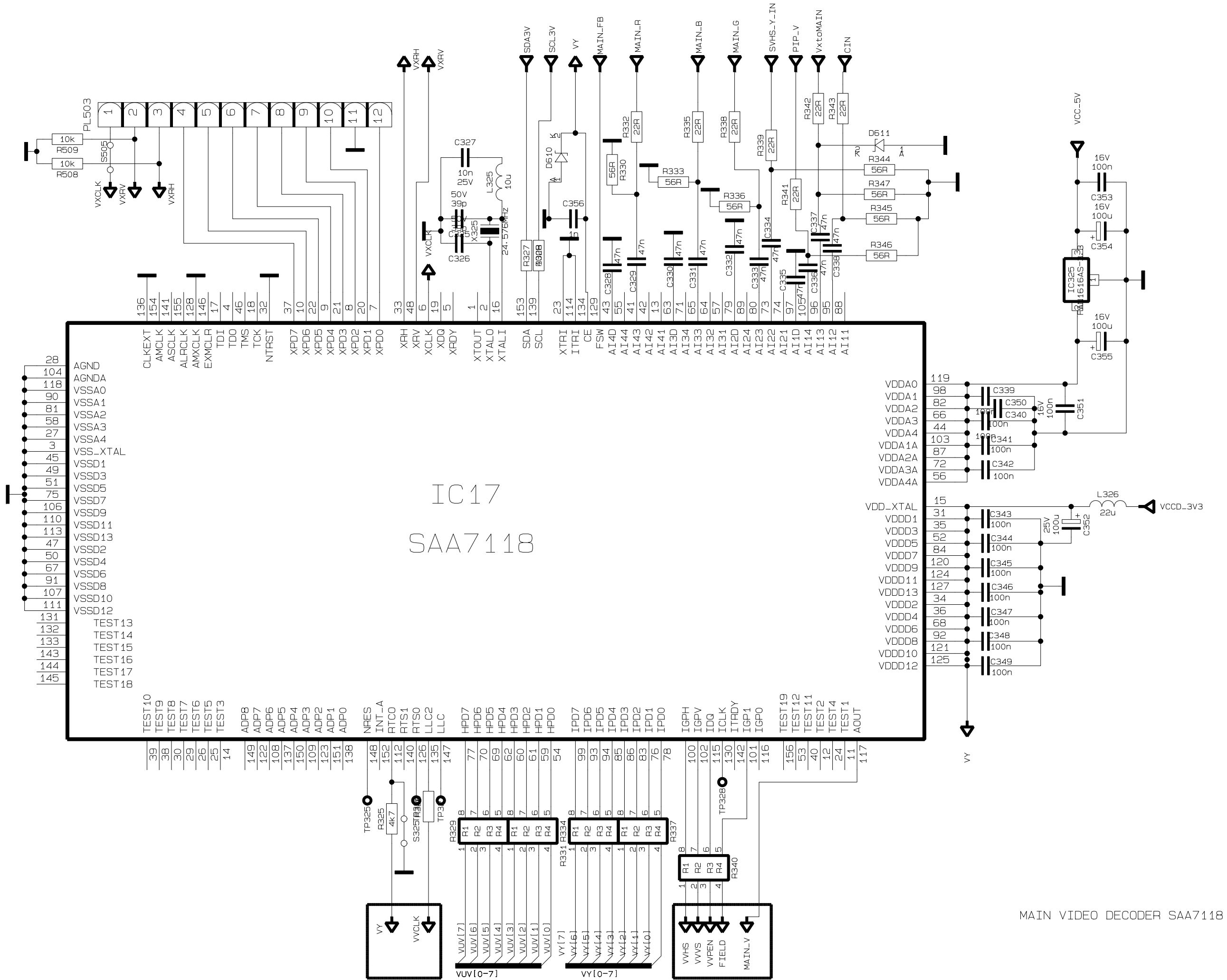
**2. SCART 2 CVBS OUT**

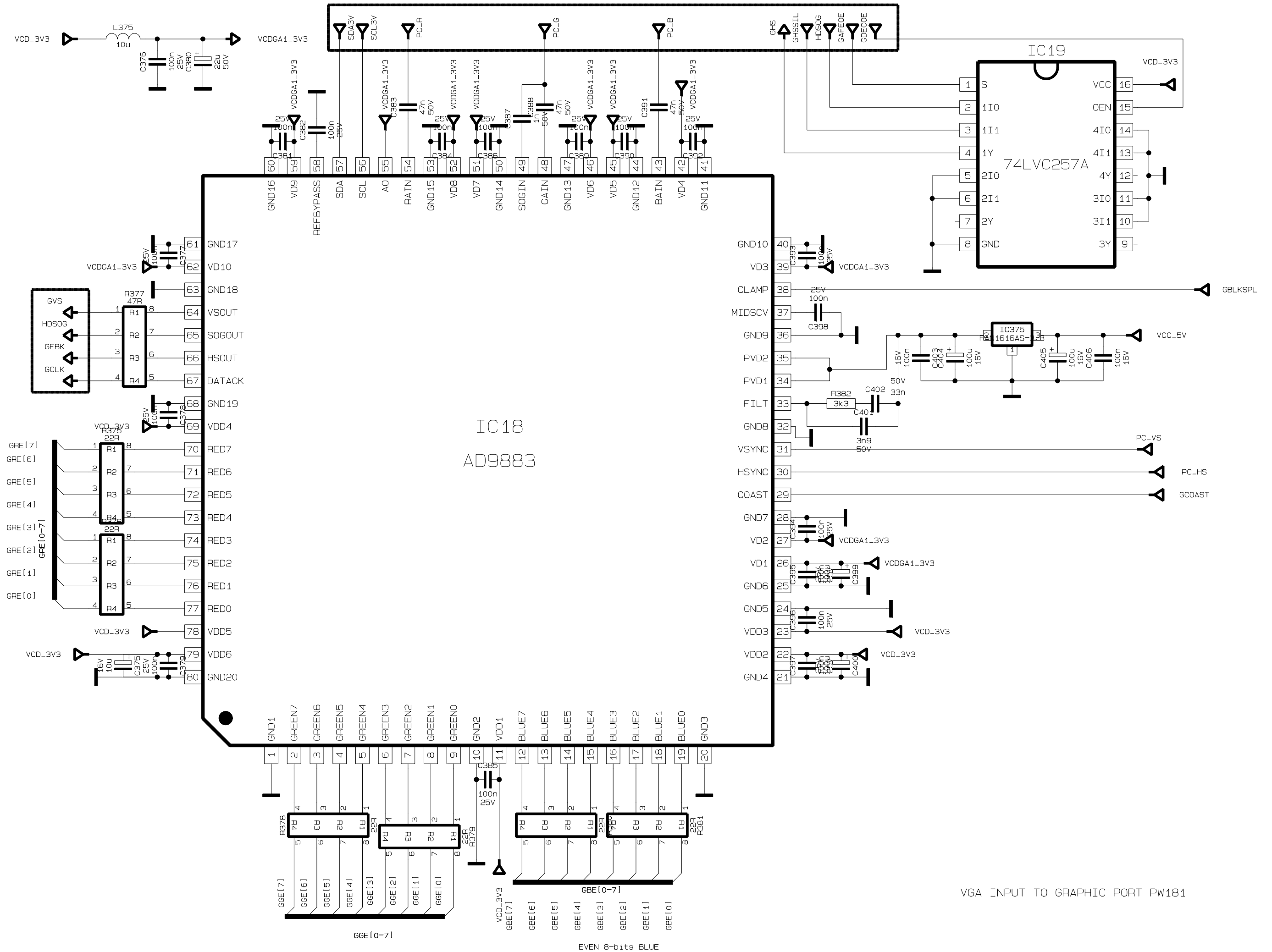
**3. AUDIO LINE OUT**

## 12. CIRCUIT DIAGRAMS

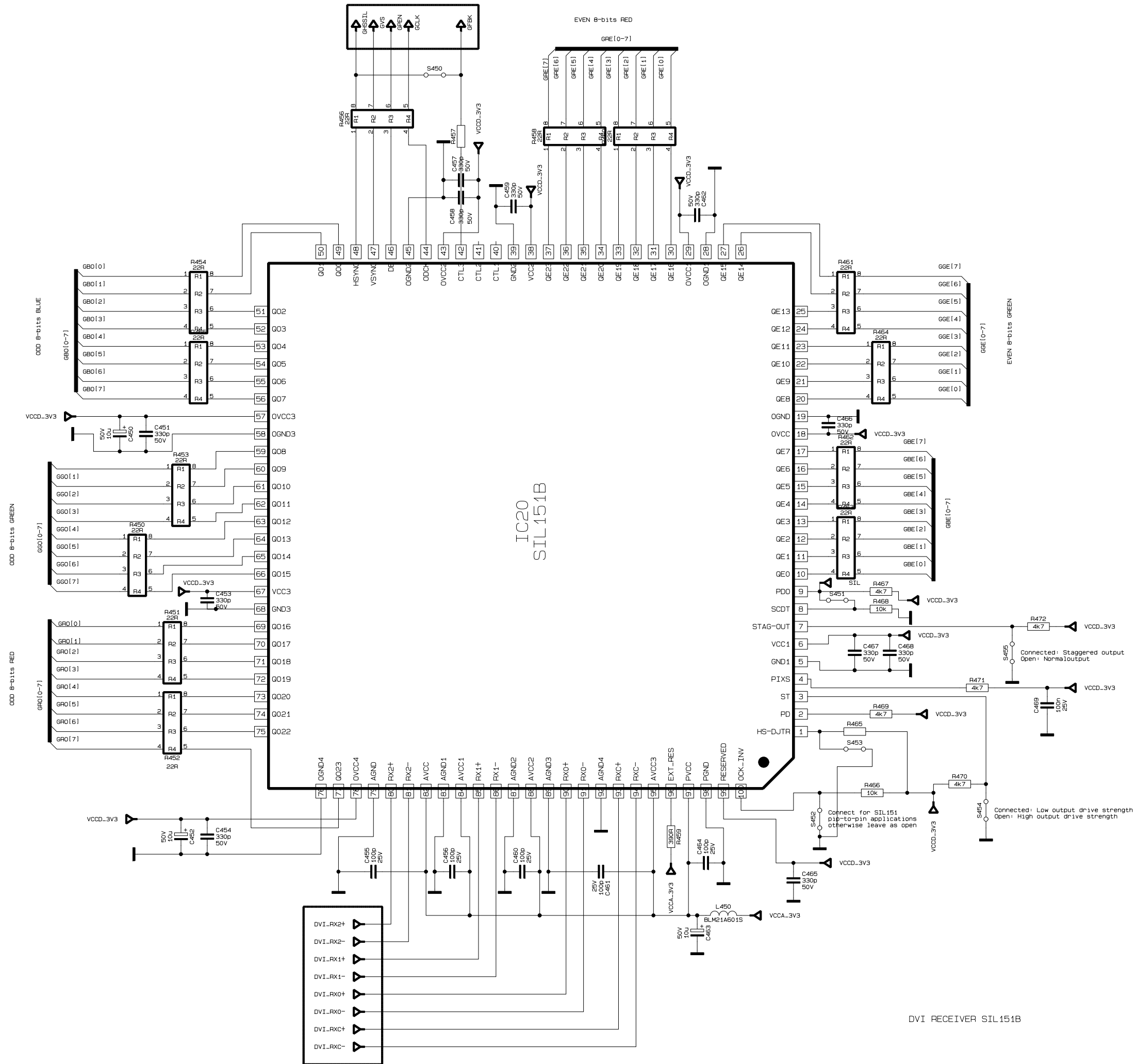




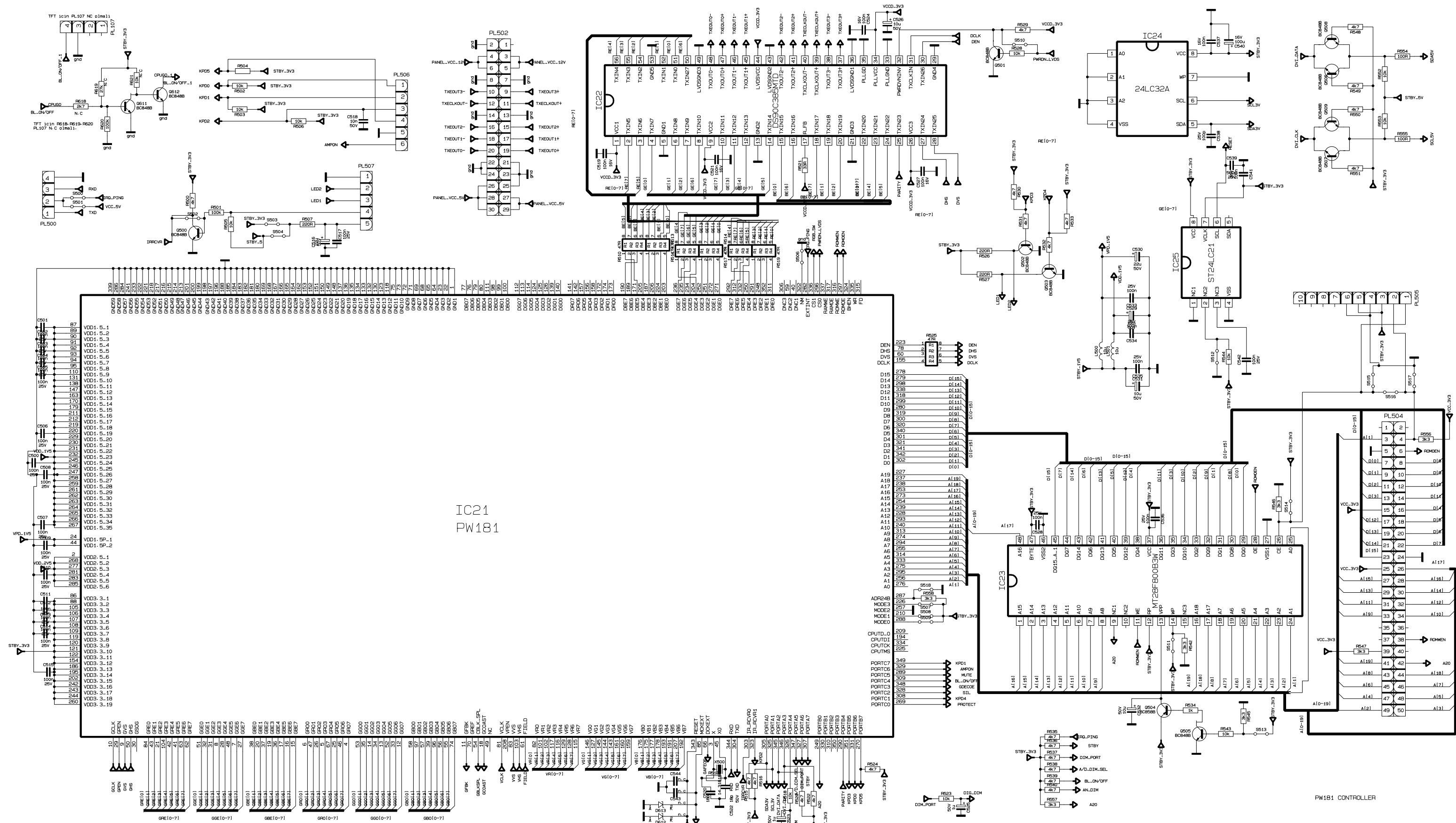




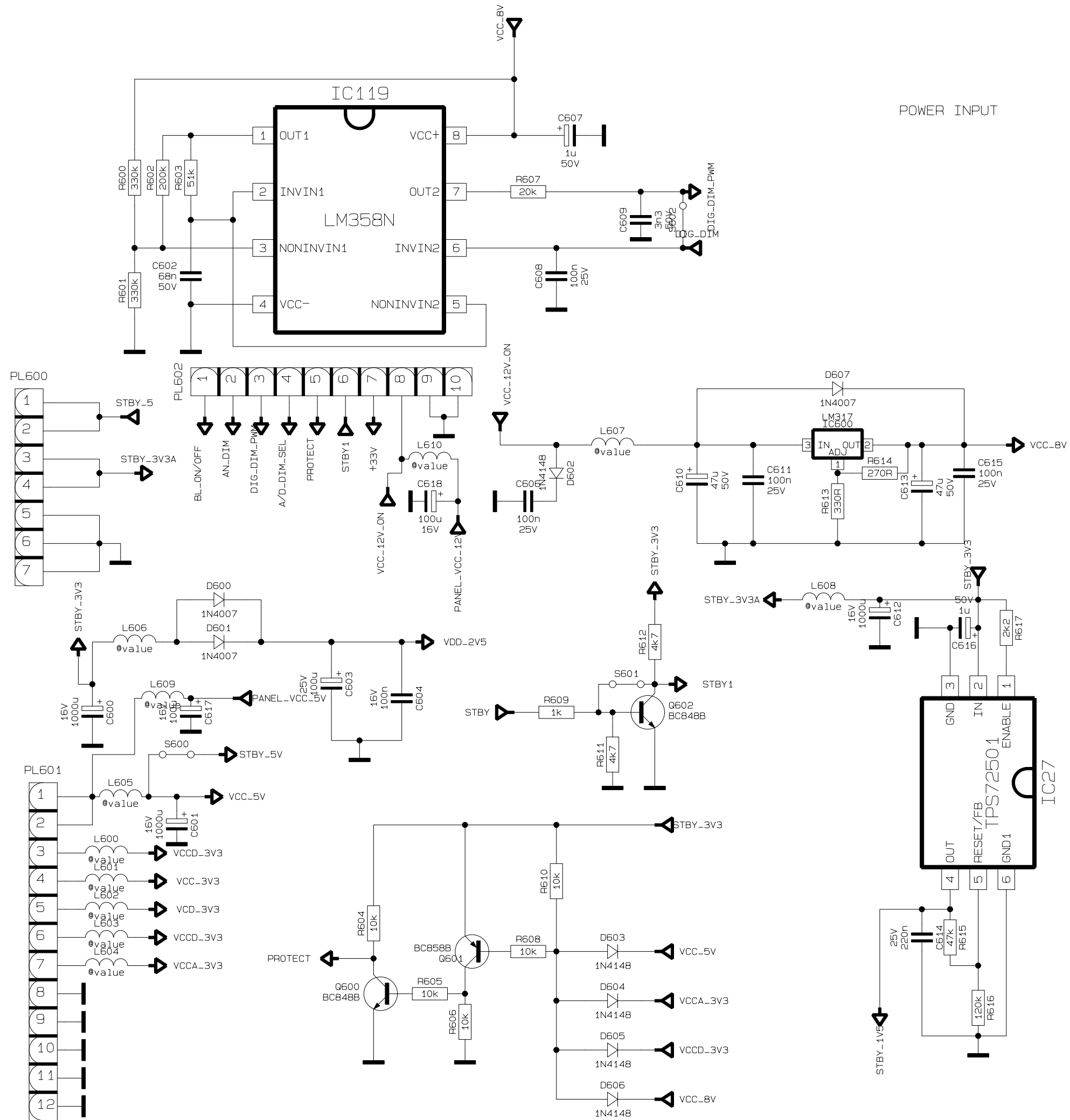
VGA INPUT TO GRAPHIC PORT PW181



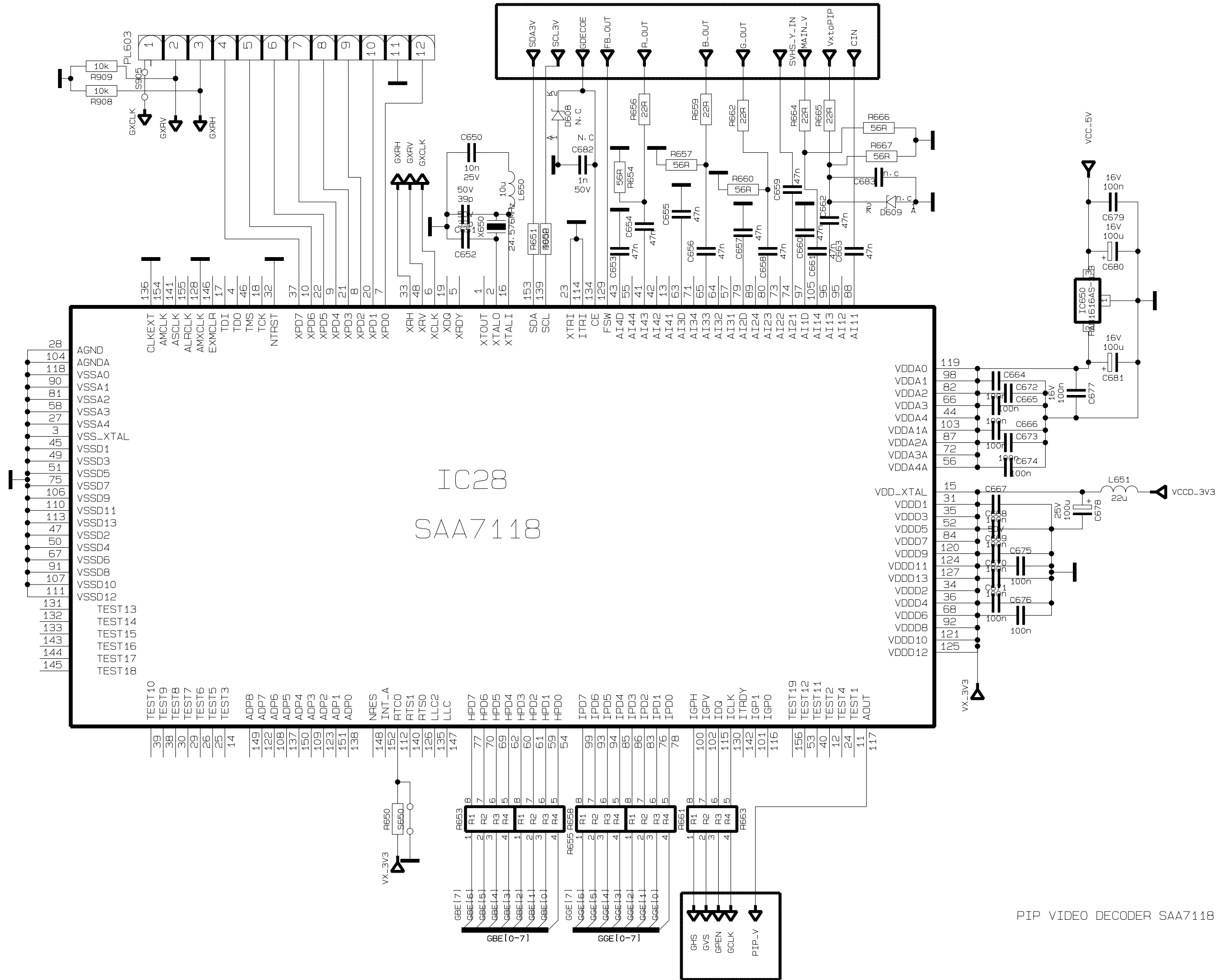
DVI RECEIVER SIL151B



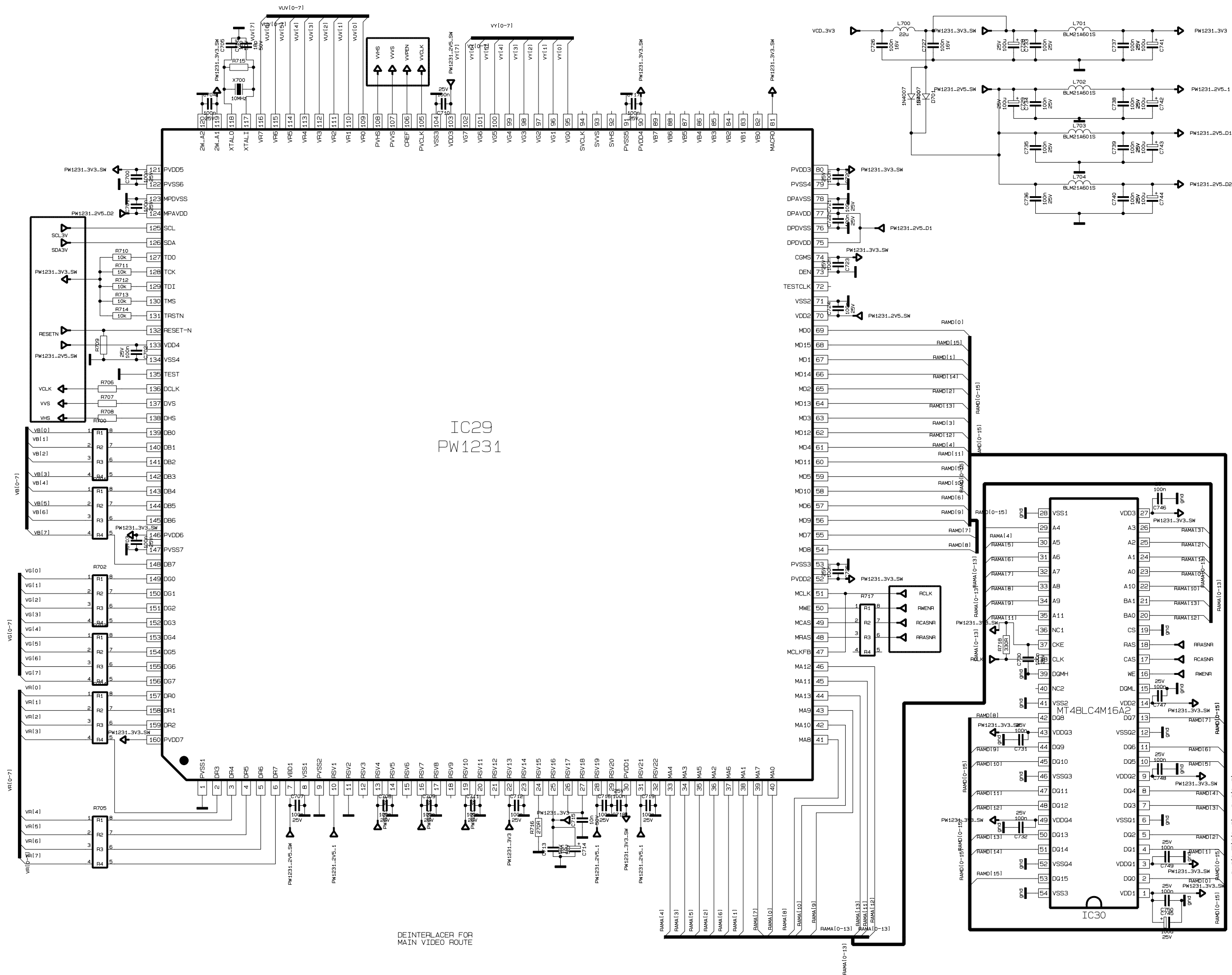
PW181 CONTROLLER

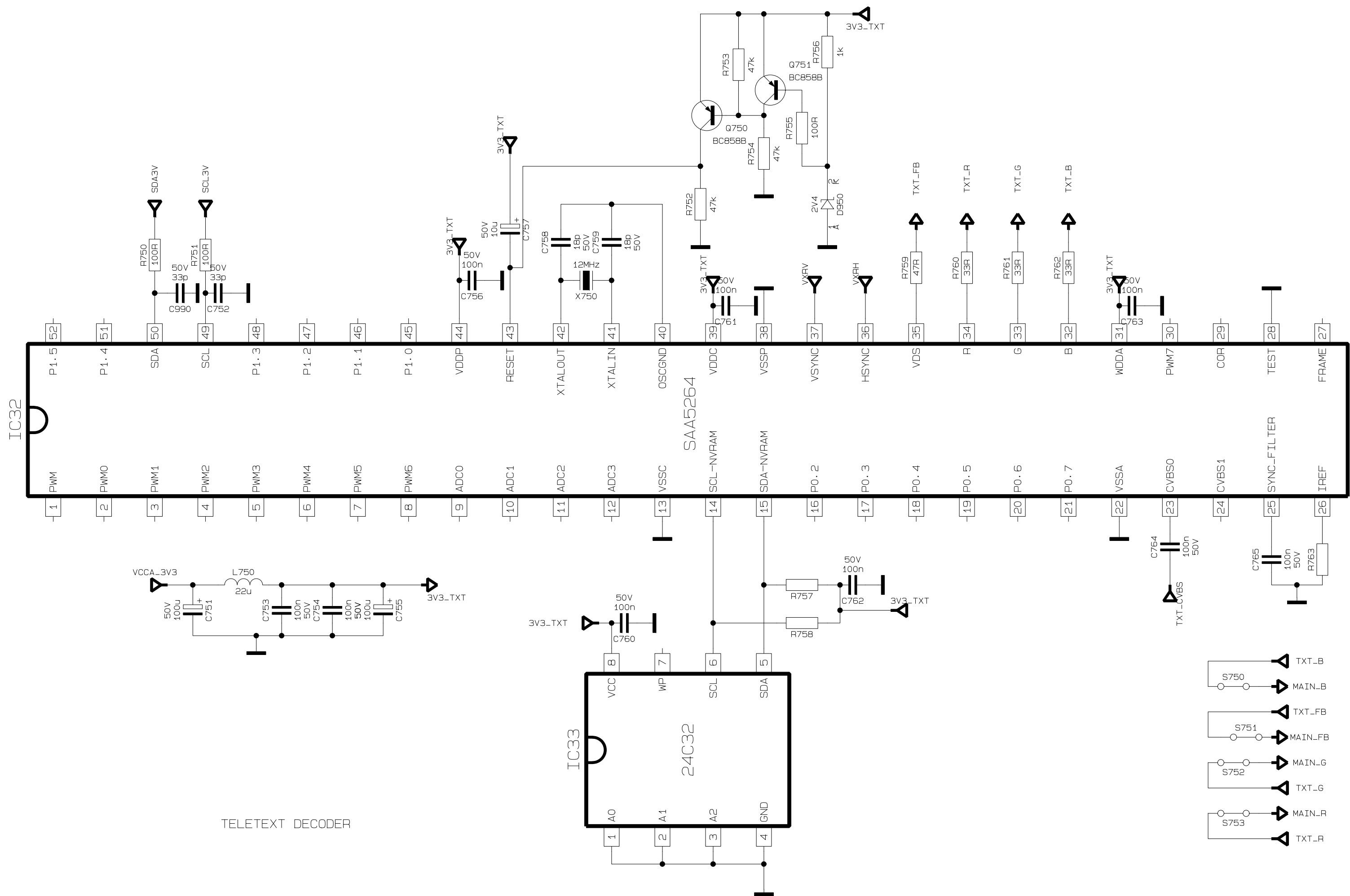






PIP VIDEO DECODER SAA7118





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